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MS-A6161 Ver:10

CPU:

Intel -Kaby Lake - U Platform

OnBoard Chipset:

HD Audio Codec:ALC887 CG

LAN:Intel WGI219V

SIO : NUVOTON NCT6104

CARD READER :Realtek RTS5249

Single Touch MER4485

Main Memory:

DDR4(2133MHz) * 1

Expansion Slots:

M.2 Slot Type 2230, Key E, * 1

PWM:

Controller:ON Semiconductor/NCP81206MNTXG 1+1+1 Phase

Controller:NB685GQ CPU_VTT

Controller:NB685GQ VCC_DDR

Other:

VGA * 1

eDP * 1

USB2.0 * 6(colay with USB 3.0 * 4)

USB3.0 * 4

SATA 3.0 * 1(HDD)

SATA 2.0 * 1(ODD)

LPT Port * 1

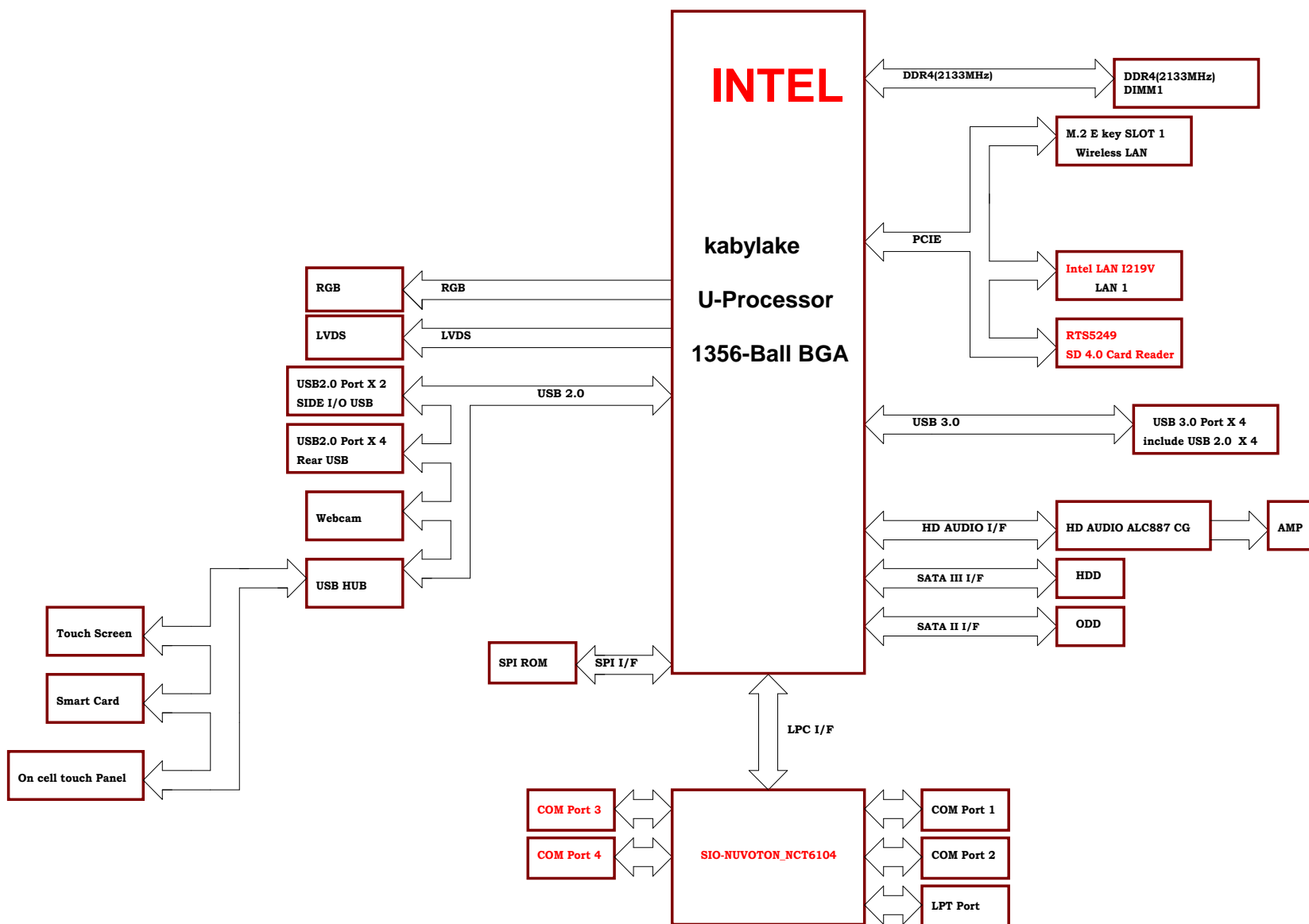
COM Port * 4

Card reader * 1(3 in 1)

Smart Card * 1

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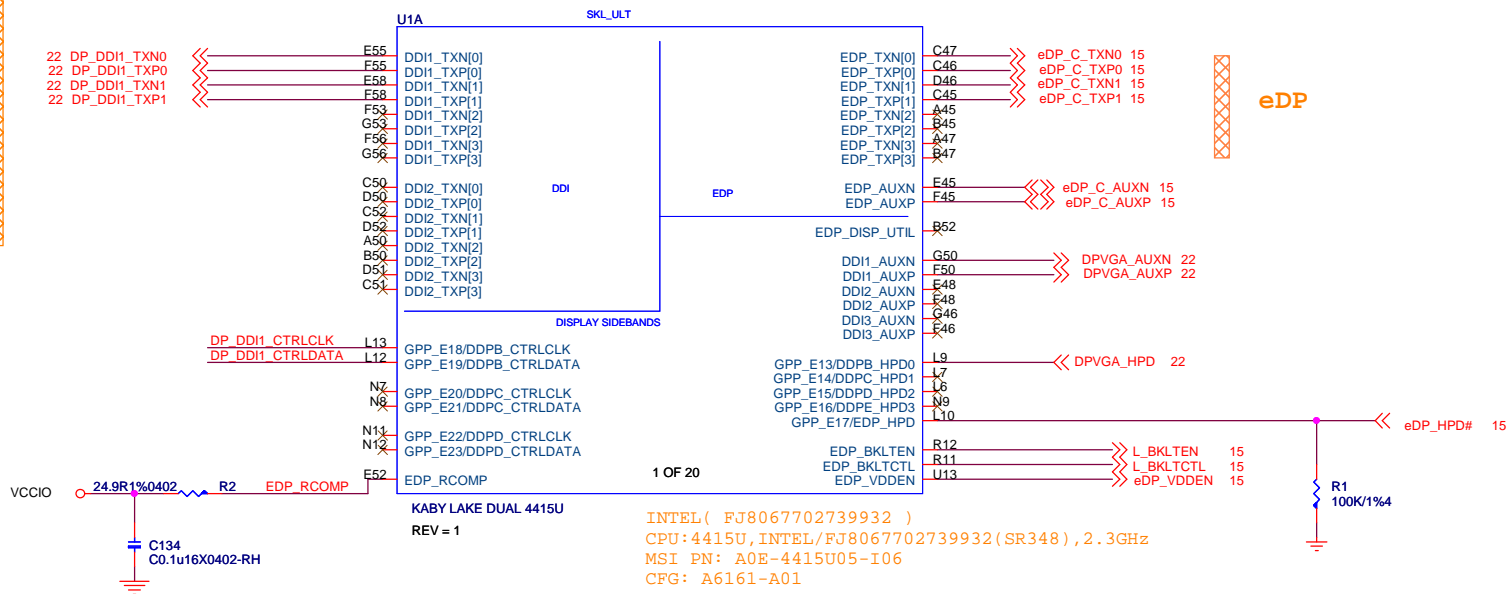
Block Diagram



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DP to VGA



INTEL(FJ8067702739932)
CPU:4415U,INTEL/FJ8067702739932(SR348),2.3GHz
MSI PN: A0E-4415U05-I06
CFG: A6161-A01

U1-3865U

CPU1

KABY LAKE DUAL 3865U

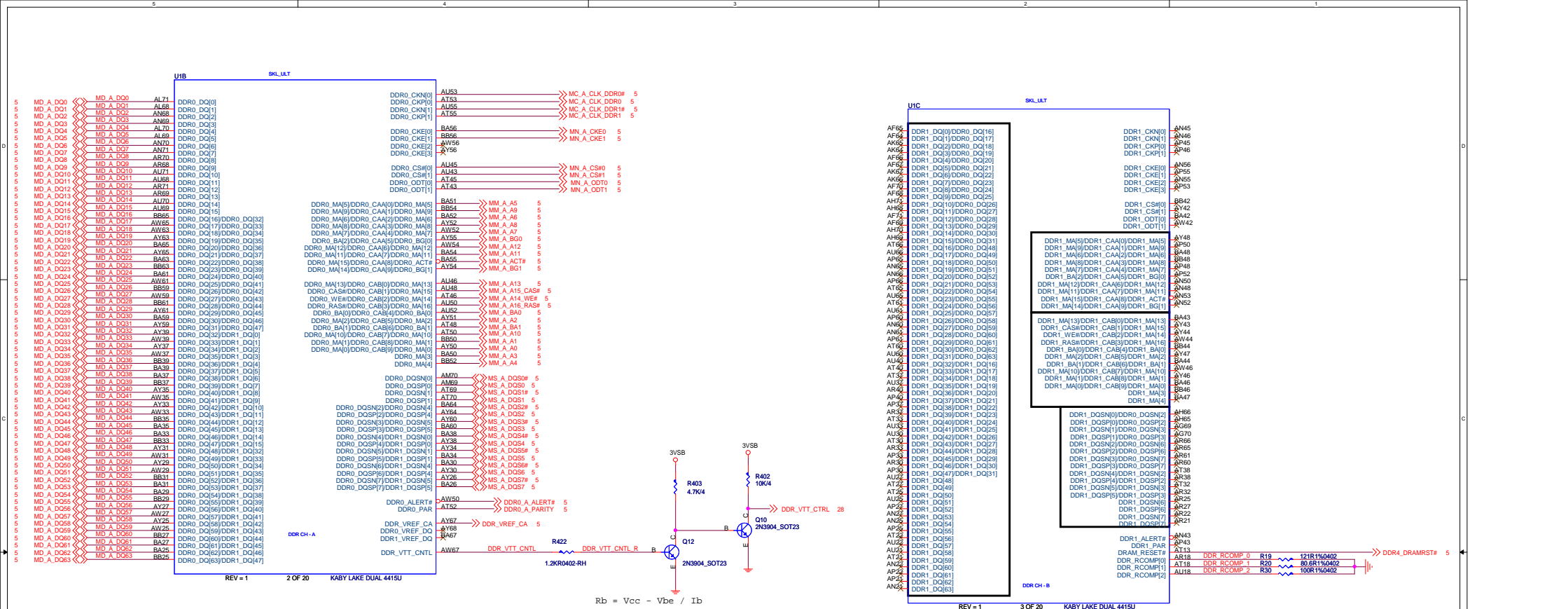
INTEL(FJ8067702739933)
CPU:3865U,INTEL/FJ8067702739933(SR349),1.8GHz
MSI PN: A0F-3865U05-I06
CFG: A6161-A02



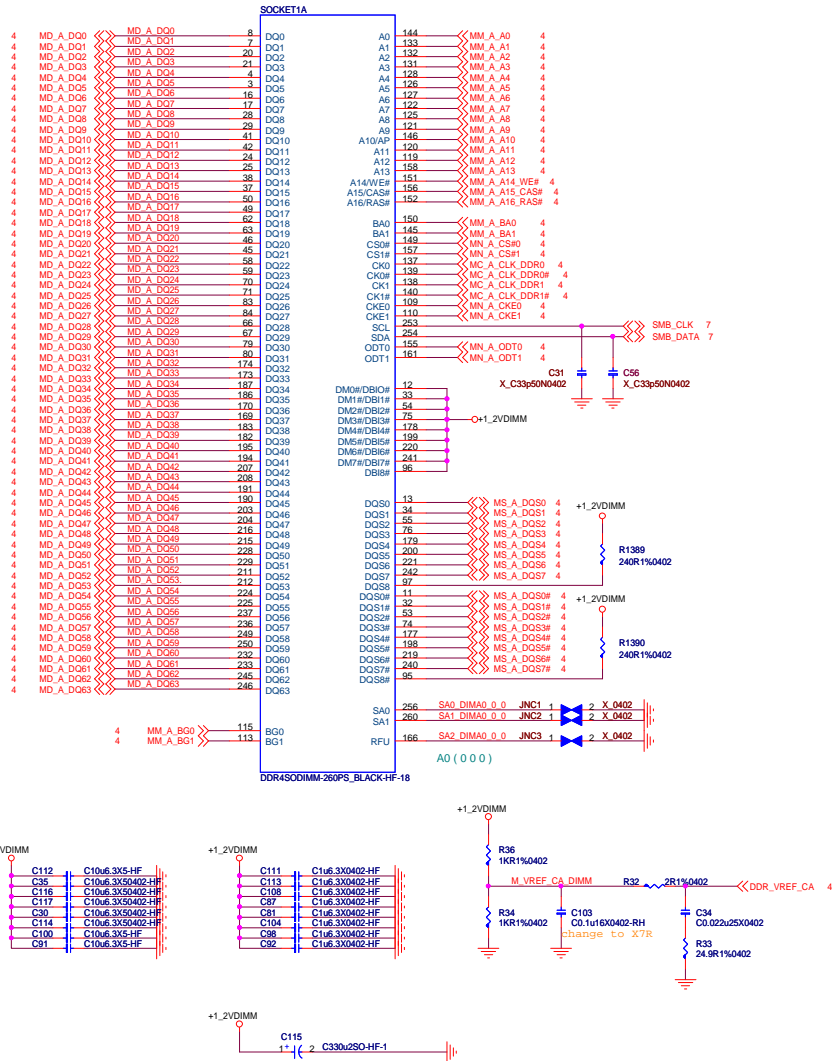
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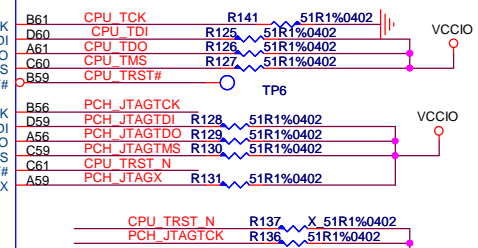
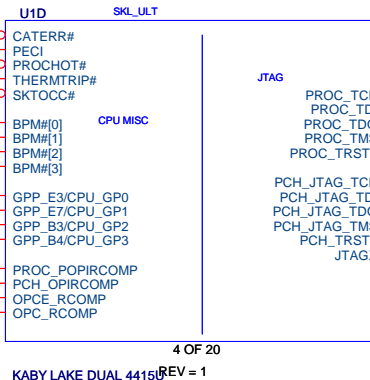
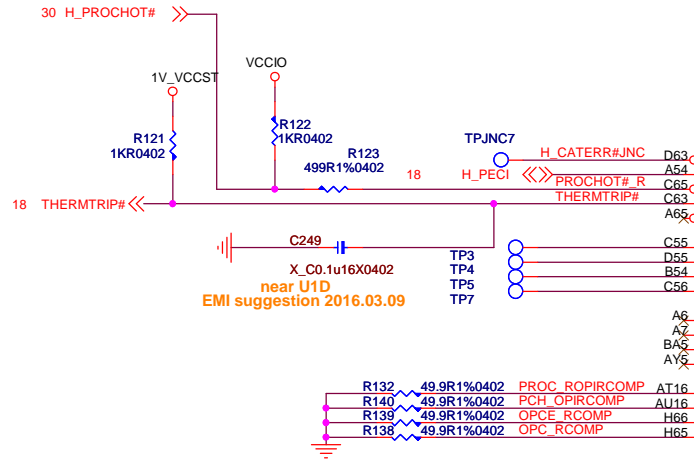
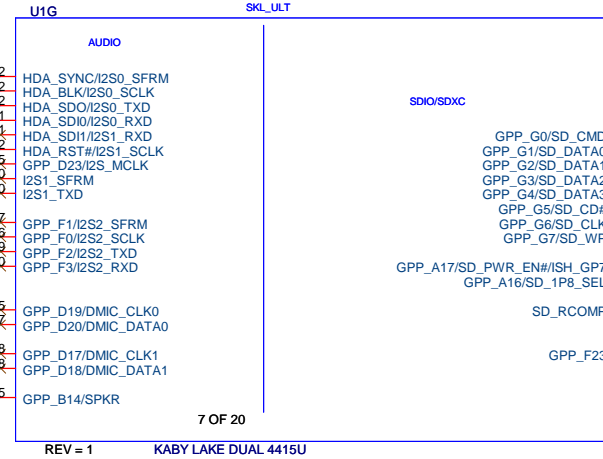
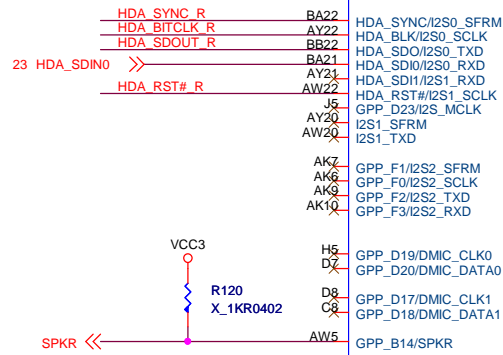
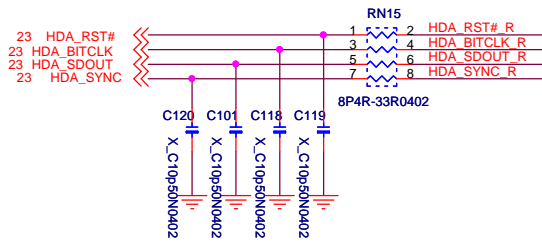
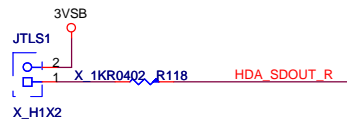
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SODIMM_A0 (Standard) H:5.2 mm
MSI PN:N13-2600160-CK3
Footprint: DDR4_SODIMM260P_H5_2_6



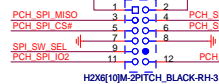
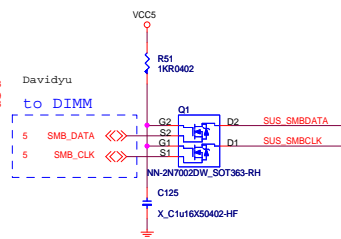
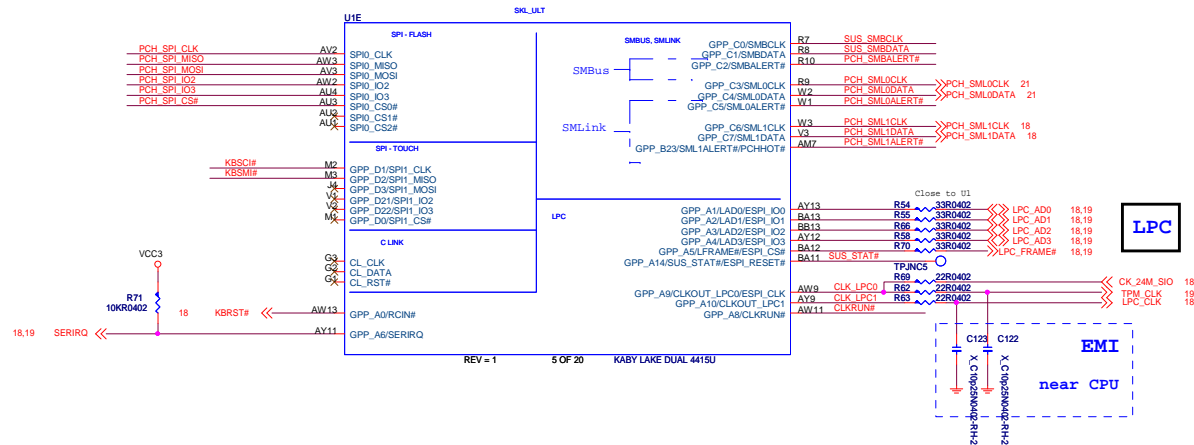
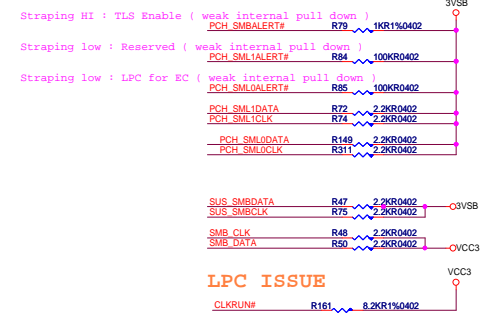
Flash Descriptor Security Override	
HDA_SDO	Low = Disable High = Enable



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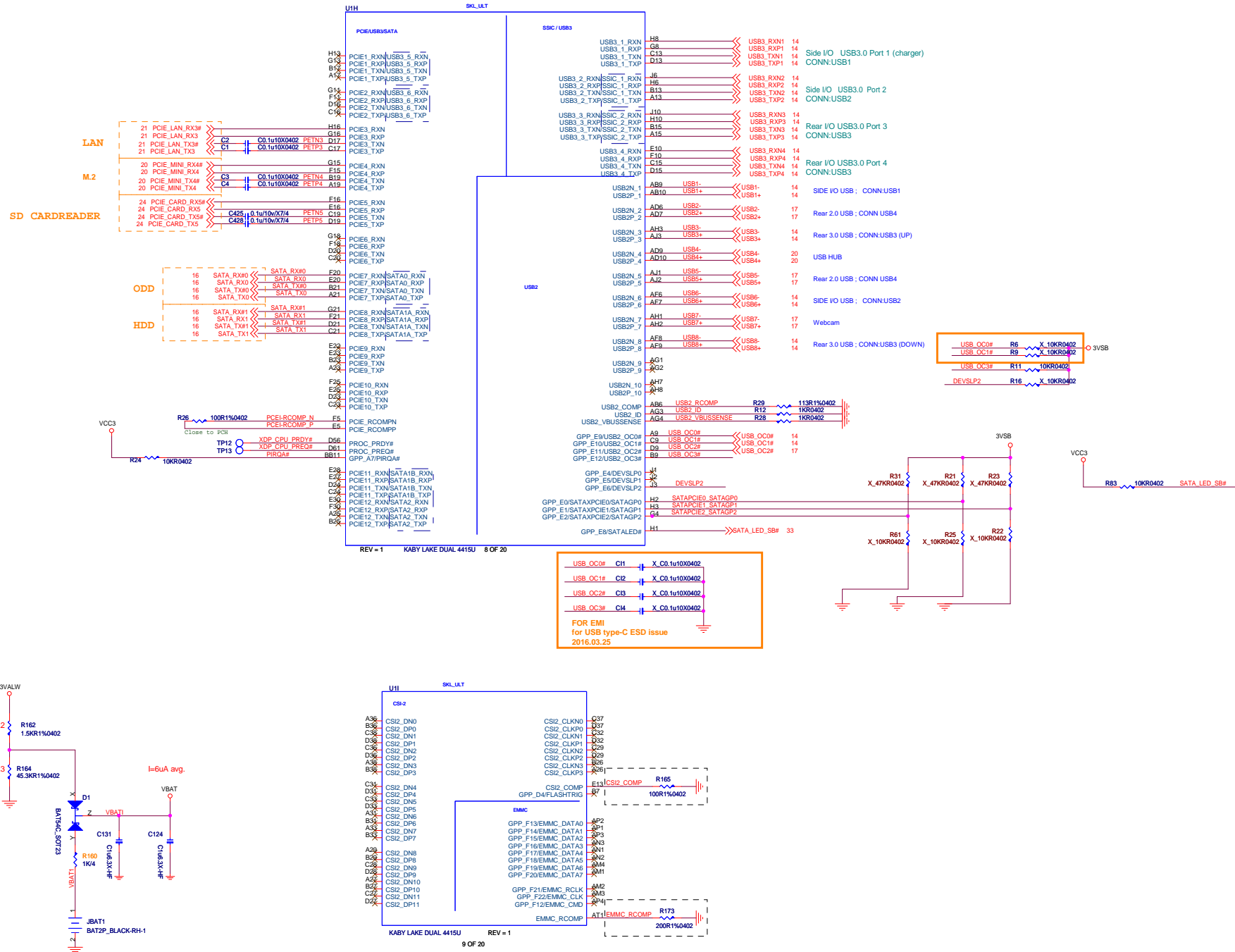


Figure 29-2, shows one option utilizing a resistor divider network (R2 and R3) at VCCDSW_3p3 to drop the voltage and meet the max VCCRTC < 3.2V specification. The cost impact is small but this solution will result in an ~0.25 mW power loss in non-G3 state. In this solution, the dual diodes must be in a single Si package to ensure matched Vf characteristics. Initial resistor value recommendations are R2=1.5 KΩ and R3=45 KΩ.

GPIO27
Connect this signal on PCH to EC. This signal resides in the DSW rail and can be used to wake the system from Deep Sx.

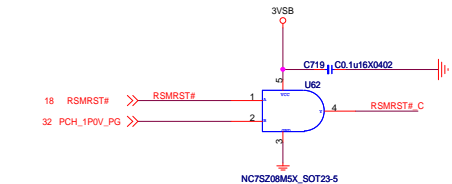
GPIO12
This signal may optionally be connected to a switch to turn 3.3-V PHY power off when LAN is disabled for additional power savings.

GPIO15:
This signal has an integrated weak pull-down (20KΩ nominal) resistor to enable Intel ME Crypto Transport Layer Security (TLS) cipher suite with no confidentiality.

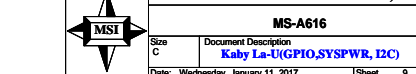
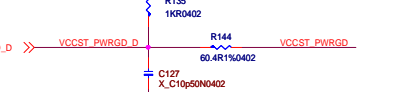
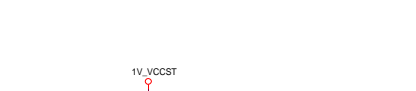
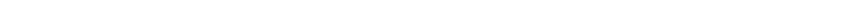
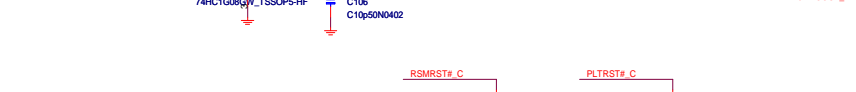
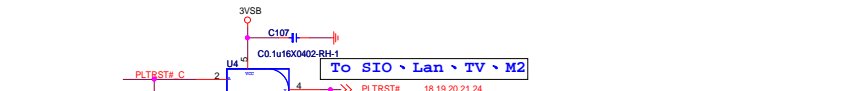
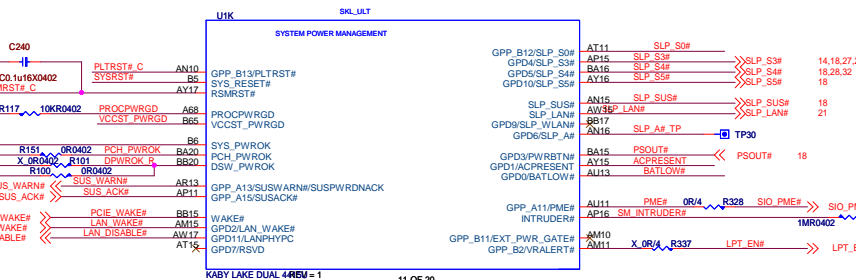
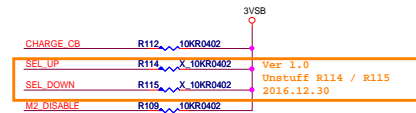
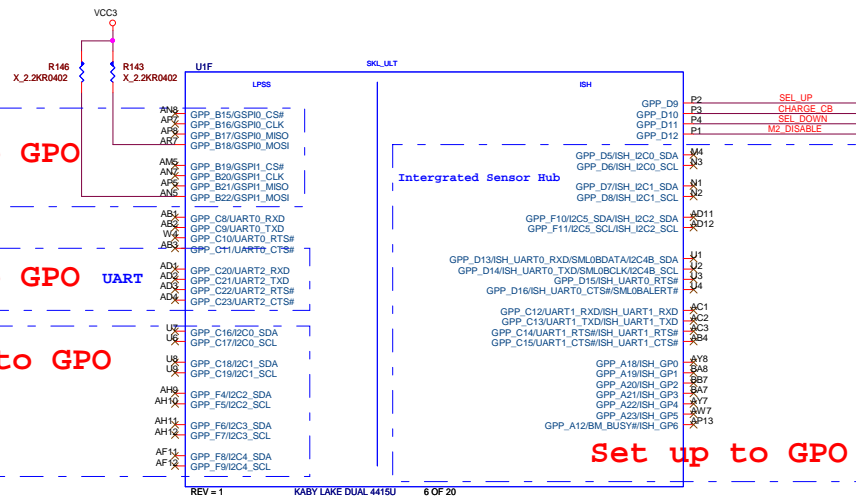
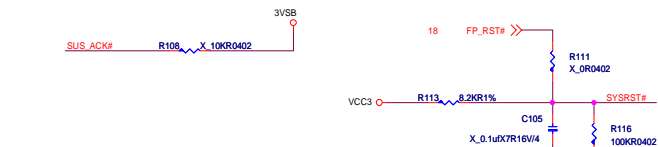
GPIO17: This power can be shut off when PCH drives HSIOPC low during S0 idle condition. external resistor is required for out put de-glitch during power sequencing.

GPIO81: This signal has an integrated weak pull-down (20KΩ nominal) to enable reboot on TCO Timer expiration.
Pull up to VCC3_3 through a 1K to 8.2KΩ ± 5% resistor to disable this capability.

SLP_S3#	No pull-up/pull-down resistors needed. Signals driven by the PCH.
SLP_S4#	
SLP_S5#	



SUS_WARN# R104 10K0402 SUS_ACK#



CFG4	1: Disabled; No Physical Display Port attached to Embedded Display Port (NC in DG) 0: Enabled; An external Display Port device is connected to the Embedded Display Port (Pull down to GND through a 1K ± 5% resistor)
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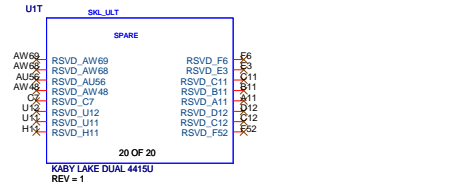
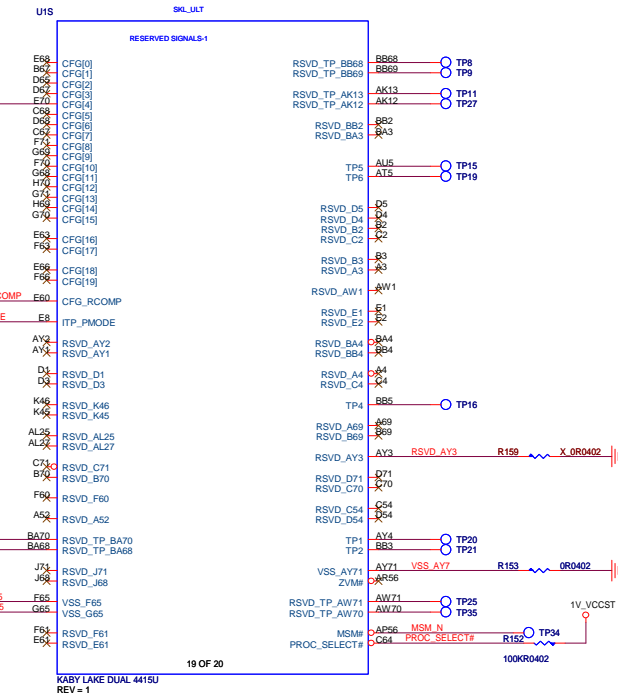
Functional Strap Definitions (Sheet 1 of 3)

Signal	Usage	When Sampled	Comment
SPWR / GPP_B14	Top Swap Override	Rising edge of PCH_PWDOK	This signal has a weak internal pull-down. 0 = Disable "No Swap" mode. (Default) 1 = Enable "No Swap" mode. This mode is address to allow the SPI and firmware hub, so the processor software defines the alternate bus flow control of the original boot block. PCW will invert A16 (default) for cycle going to the upper set of 48 blocks in the A16 or the appropriate address line (A16, A17, or A18) is selected in Top Swap block size self strap. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. Software will not be able to clear the Top Swap bit until the system is rebooted. 3. The output of this strap is readable using the top swap bit (Read, Default: Function, Offset 0x, 0x00000000). 4. This signal is in the primary well.
GPFD_M0SE / GPP_B10	No Reboot	Rising edge of PCH_PWDOK	This signal has a weak internal pull-down. 0 = Disable "No Reboot" mode. (Default) 1 = Enable "No Reboot" mode. This function is useful when connecting to the TCO (Timer system reboot feature). This function is useful when connecting to the TCO. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
SMALERT# / GPP_C2	TLS Config. Security	Rising edge of RCRST#	This signal has a weak internal pull-down. 0 = Disable Intel HEC Crypt Transport Layer Security (TLS) other suite (no confidentiality). (Default) 1 = Enable Intel HEC Crypt Transport Layer Security (TLS) other suite (with confidentiality). Must be selected to support SPI with TLS. (Note: Intel does not support confidentiality in this mode.) Notes: 1. The internal pull-down is disabled after RCRST# de-asserts. 2. This signal is in the primary well.

Functional Strap Definitions (Sheet 2 of 3)

Signal	Usage	When Sampled	Comment
GPFI_M0SE / GPP_B22	Boot BIOS (Deep S3)	Rising edge of PCH_PWDOK	This signal has a weak internal pull-down. This field determines the destination of accesses to the BIOS memory range. Also controllable using Boot BIOS Destination bit (Boot, Default: Function, Offset 0x, 0x00000000). 0 = SPI (Default) 1 = LPC Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. If option 1 (LPC) is selected, BIOS may still be placed and LPC, but all platforms are required to have SPI flash connected directly to the PCW's SPI bus with a valid descriptor in order to boot. 3. Boot BIOS destination related to LPC functional strap or using Boot BIOS Destination bit will not affect SPI accesses initiated by Intel ME or Integrated GSD LAN. 4. This signal is in the primary well.
SPMLALERT# / GPP_C5	SPFI or LPC	Rising edge of RCRST#	This signal has a weak internal pull-down. 0 = LPC is selected for IC. (Default) 1 = SPFI is selected for IC. Notes: 1. The internal pull-down is disabled after RCRST# de-asserts. 2. This signal is in the primary well.
SPFI_M0SE	Reserved	Rising edge of RCRST#	This strap should sample HSGH. There should NOT be any on-board device driving it to opposite direction during strap sampling. This signal has an internal pull-up.
SPFI_M0SO	Reserved	Rising edge of RCRST#	This strap should sample HSGH. There should NOT be any on-board device driving it to opposite direction during strap sampling. This signal has an internal pull-up.
SPMLALERT# / PCHROT# / GPP_B03	Reserved	Rising edge of RCRST#	This strap should sample L0SW. There should NOT be any on-board device driving it to opposite direction during strap sampling. This signal has an internal pull-up.
SPFI_I02	Reserved	Rising edge of RCRST#	This strap should sample HSGH. There should NOT be any on-board device driving it to opposite direction during strap sampling. This signal has an internal pull-up.
SPFI_I03	Reserved	Rising edge of RCRST#	This strap should sample HSGH. There should NOT be any on-board device driving it to opposite direction during strap sampling. This signal has an internal pull-up.

Signal Name	Pin		Pin	Signal Name
VccSus3_3	1	o	o	SLP_S3#
VccDSW3_3	3	o	o	SLP_S5#
SLP_S4#	5	o	o	SLP_A#
VccDSW3_3	7	o	o	GND
RTCRST#	9	o	o	Ground for RTCRST#
PWRBTN#	11	o	o	Ground for PWRBTN#
SYS_RESET#	13	o	o	Ground for SYS_RESET#
SLP_S0#	15	o	o	NC
NC	17	o	o	NC



RSVD	All the RSVD pins should be left unconnected (floating) on the board.
------	---

Functional Strap Definitions (Sheet 3 of 3)

Signal	Usage	When Sampled	Comment
HDA_SDO / LPA_M0M	Flash Descriptor Security Override	Rising edge of PCH_PWDOK	This signal has a weak internal pull-down. 0 = Enable security measures defined in the Flash Descriptor. (Default) 1 = Disable Flash Descriptor Security (optional). This strap should only be inserted high using external pull-up in manufacturing/testing environments ONLY. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. After HDA_SDO high on the rising edge of PCH_PWDOK, all HDA flash management steps after Chipset bring up and disable before Intel ME boot-up. This is a Deep S3 mode and must not be entered after manufacturing/testing. 3. This signal is in the primary well.
IOPL_CTLDATA / GPP_C19	Display Port B Detected	Rising edge of PCH_PWDOK	This signal has a weak internal pull-down. 0 = Port B is not detected. (Default) 1 = Port B is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
IOPL_CTLDATA / GPP_C21	Display Port C Detected	Rising edge of PCH_PWDOK	This signal has a weak internal pull-down. 0 = Port C is not detected. (Default) 1 = Port C is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.

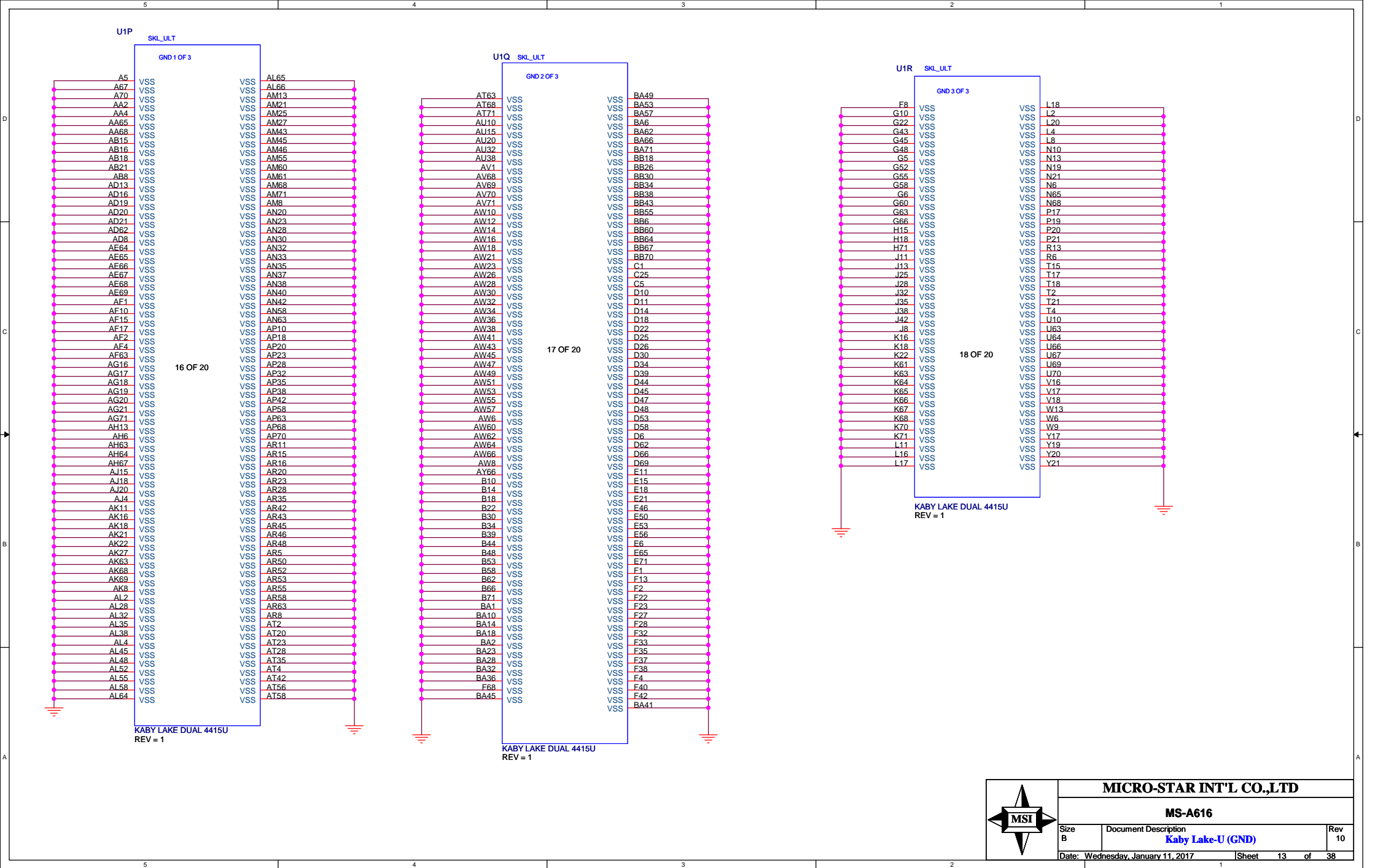
Note: Make sure you connect all 6 cables (Sus, S3, S4, S5, M1/OFF, GND) to the relevant signals on the SUT. Otherwise you will not be able to check the system's power state or perform power tests.

In addition to these signals, you can also sample additional signals on the platform by connecting them to the following cables on the main cable:

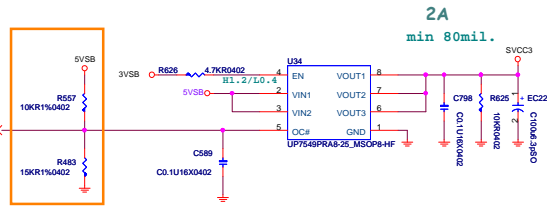
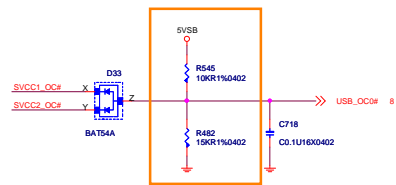
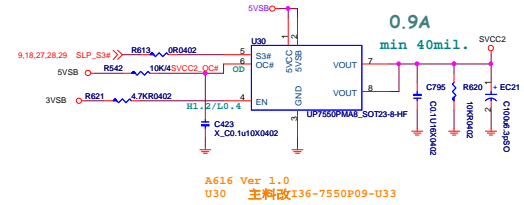
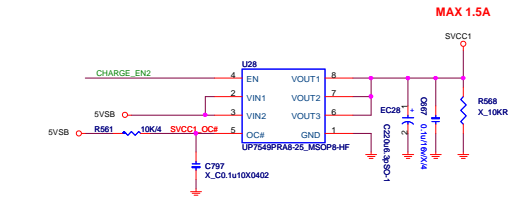
- INEX1 (Deep S4/5)
- INEX2 (Deep S3)
- INEX3
- INEX4
- INEX5

Note: If you do not connect all of the additional cables (INEX1 (Deep S4/5), INEX2 (Deep S3), INEX3, INEX4, INEX5) to the relevant signals, you must connect the unconnected cables to GND; do not leave them unconnected. Unconnected cables may give unexpected results.

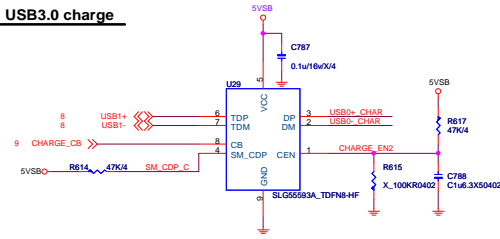
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MS-A616			
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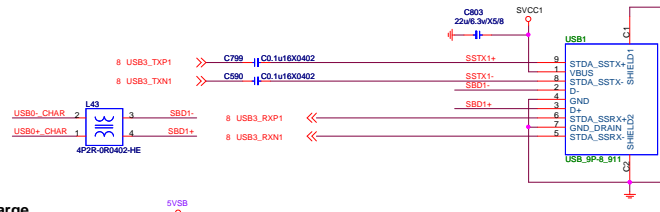
USB3.0



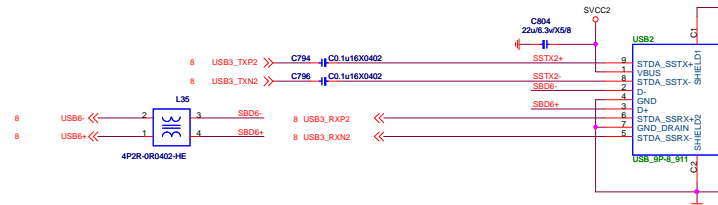
USB3.0 charge



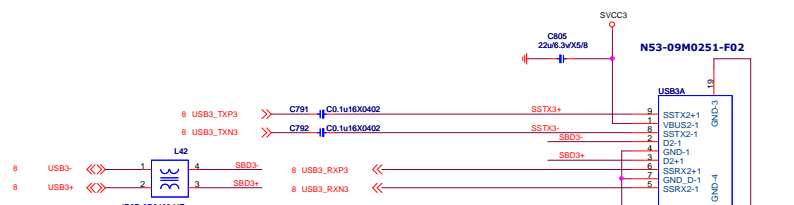
Side I/O USB3.0 (charger)



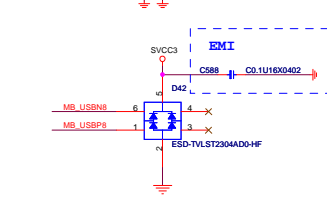
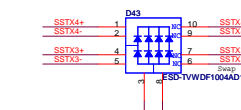
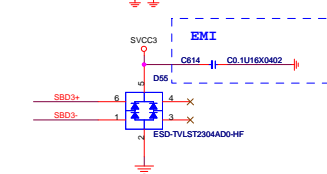
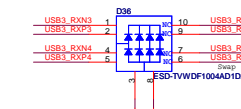
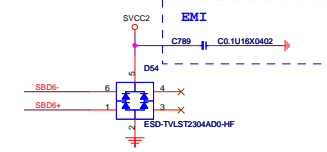
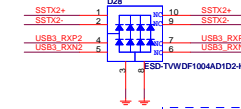
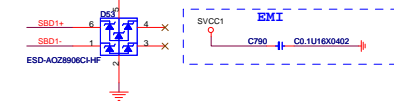
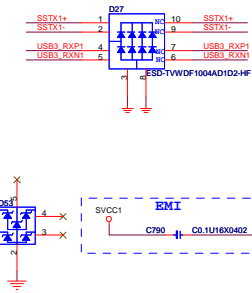
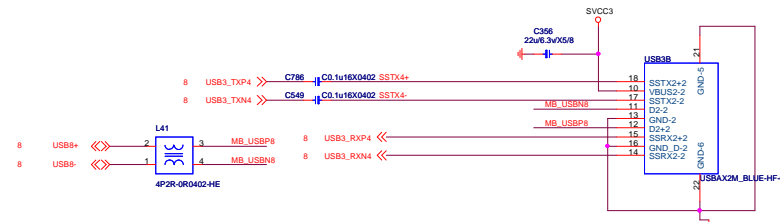
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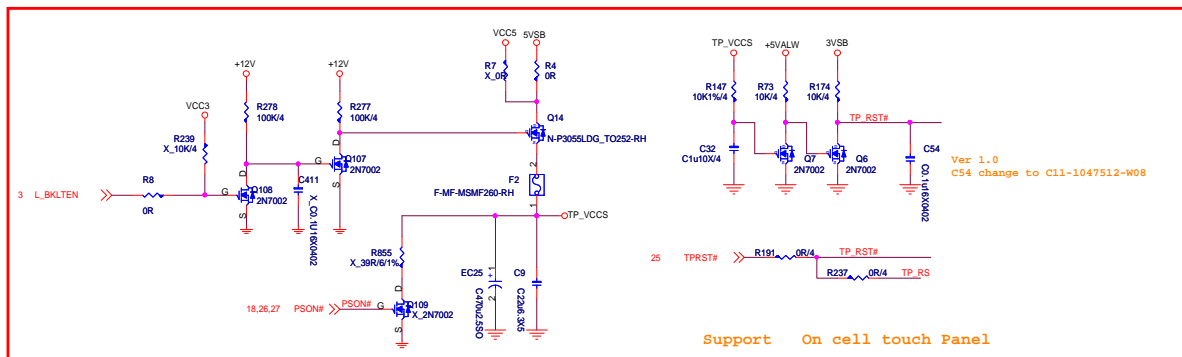
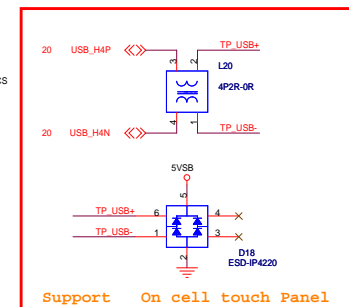
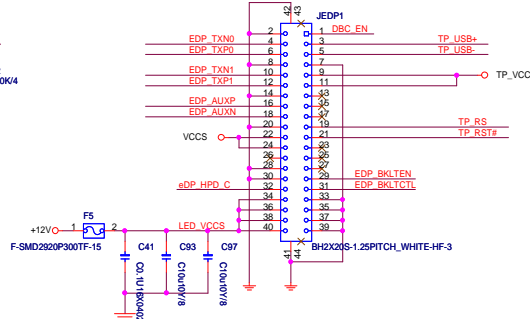
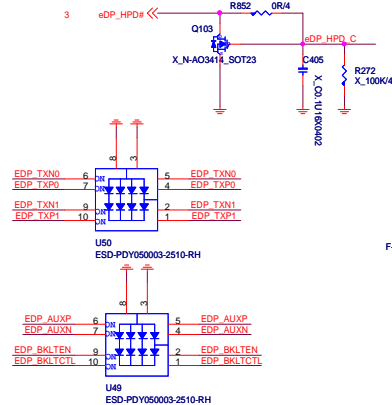
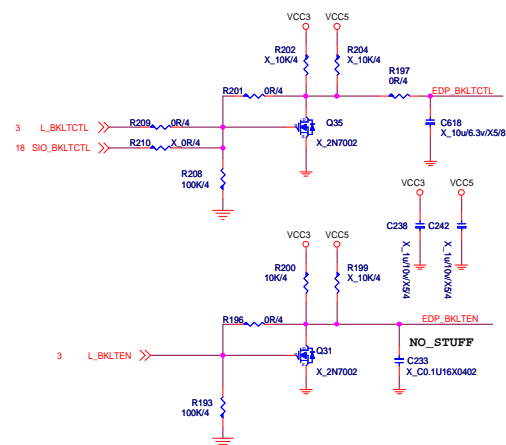
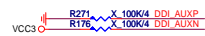
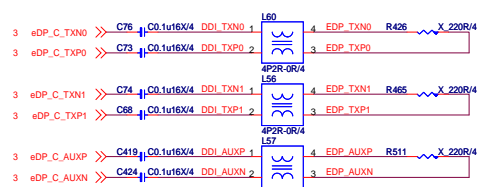
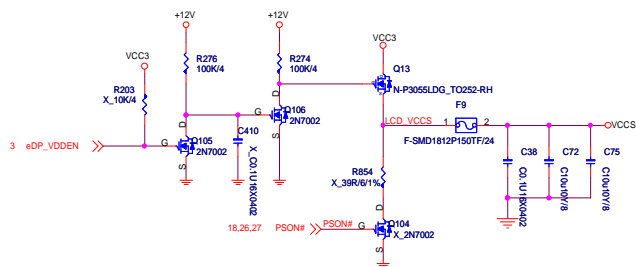


Rear I/O USB3.0



N53-18M0311-F02

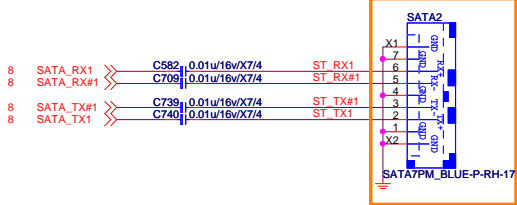




MICRO-STAR INT'L CO.,LTD			
MS-A616			
Size	Document Description	Rev	
C	eDP	10	
Date: Wednesday, January 11, 2017		Sheet	15 of 38

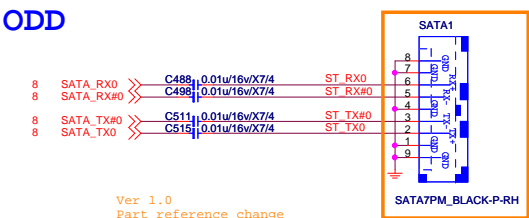
SATA HDD 2.5"

N5N-07M2101-H06(SATA1) BLUE



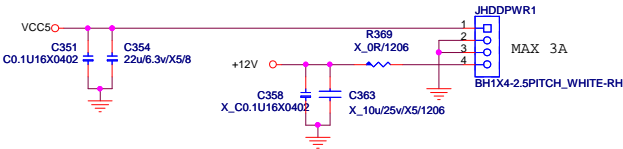
SATA ODD

N5N-07M0221-H06(SATA2) BLACK



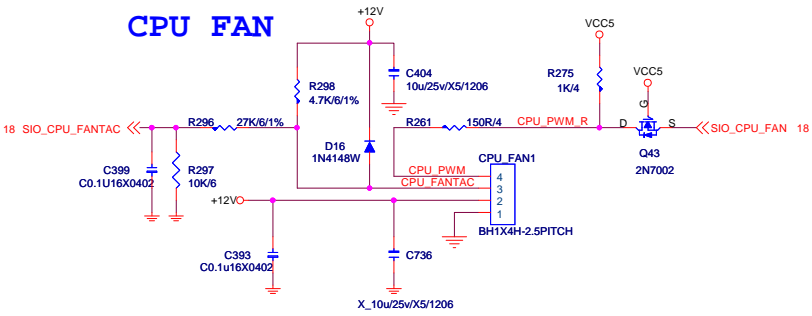
Ver 1.0
Part reference change
SATA1 : for ODD
SATA2 : for HDD

HDD Power



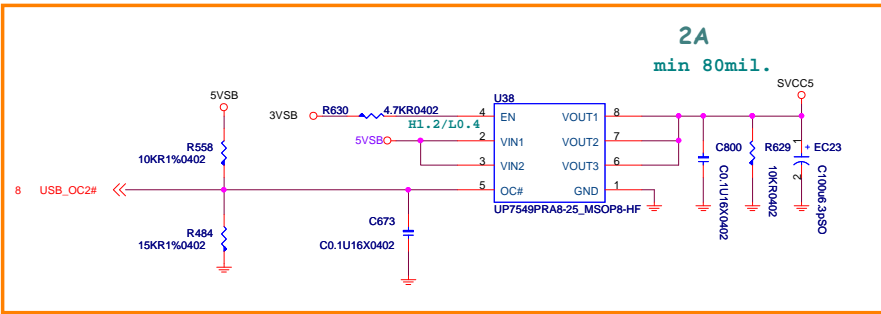
N32-1040D31-H06

CPU FAN

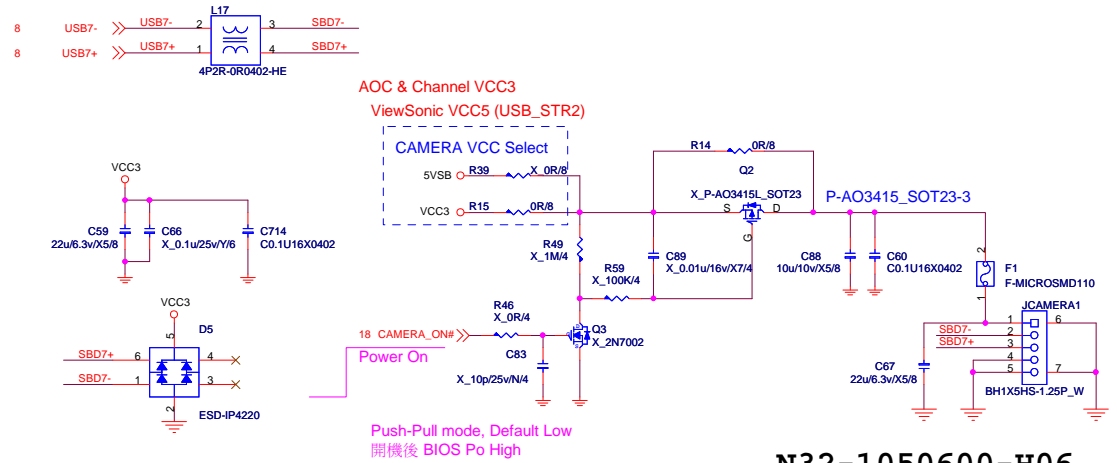


MICRO-STAR INT'L CO.,LTD		
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Size Custom	Document Description SATA / CPUFAN	Rev 10
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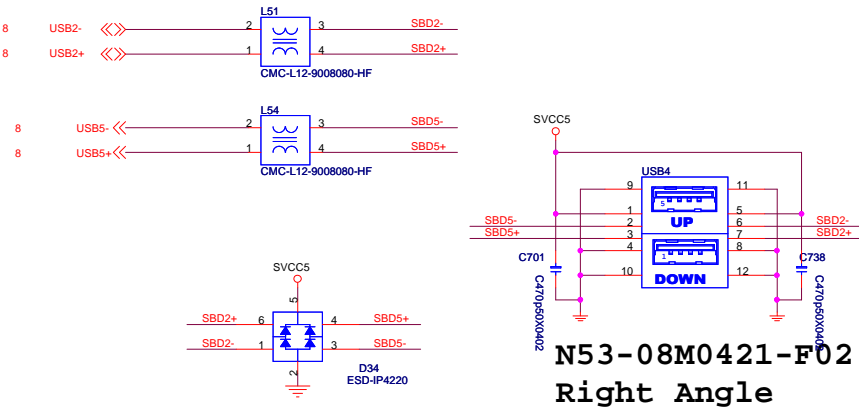
Rear I/O USB2.0 OC



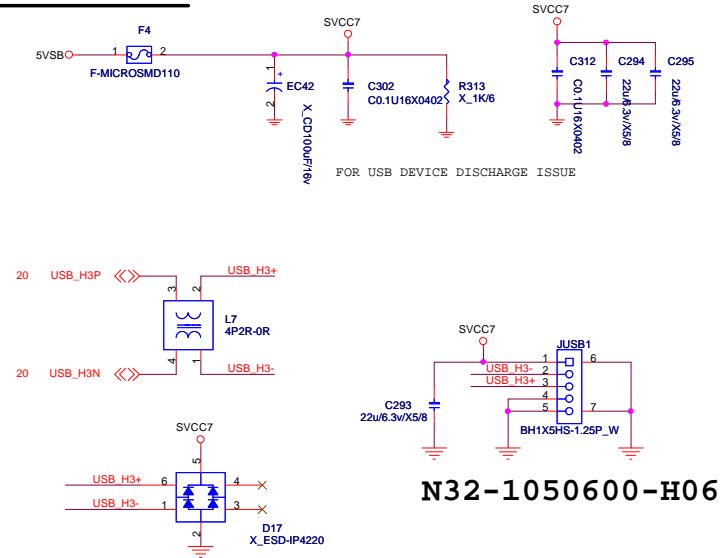
Webcam



Rear I/O USB2.0



for Smart Card



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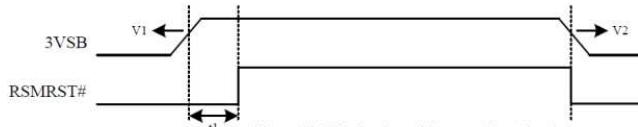
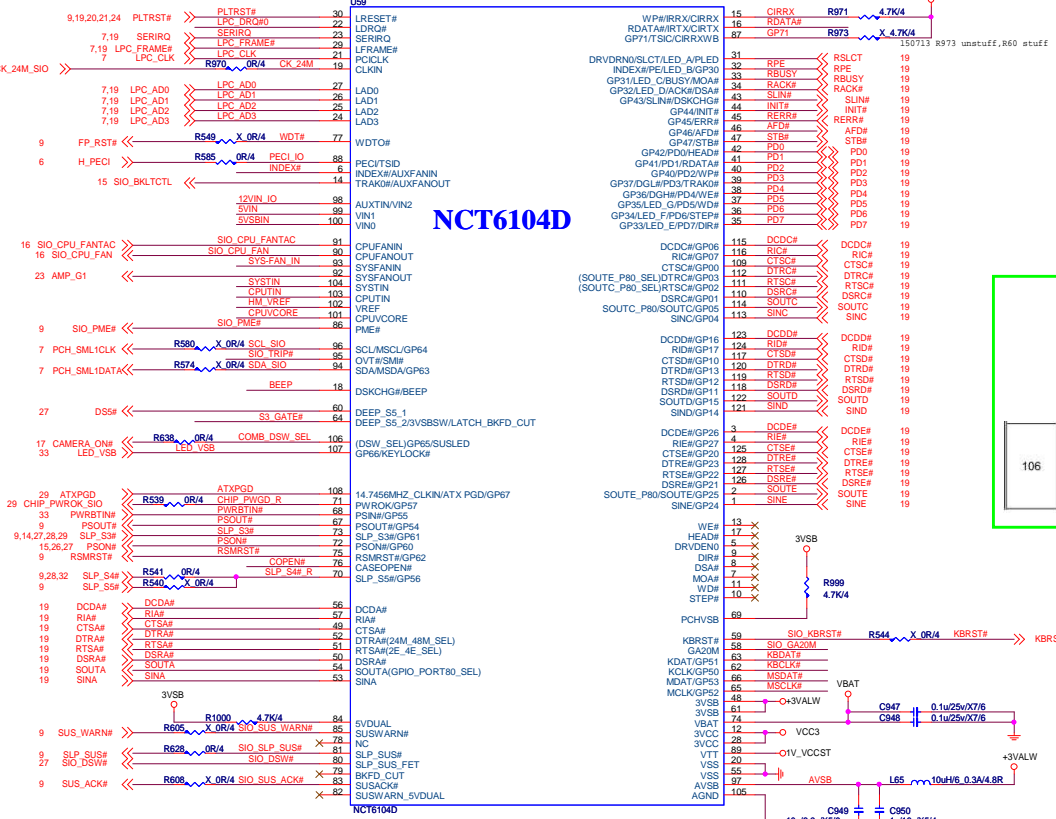
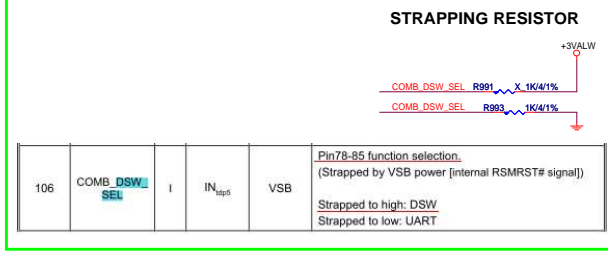
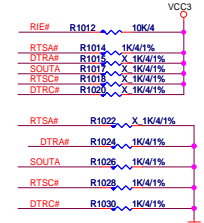
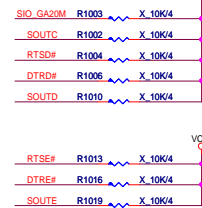
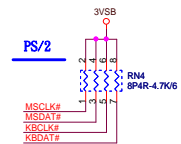
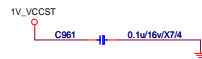
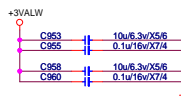
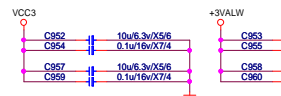
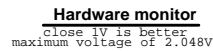
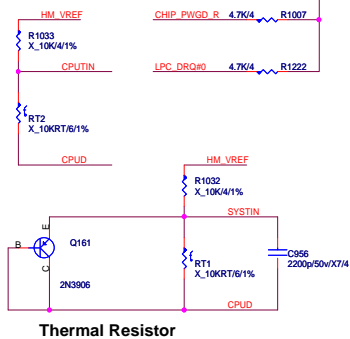


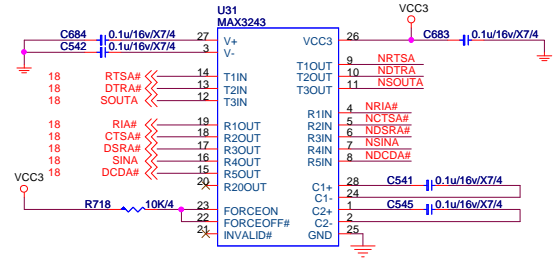
Figure 16-5 Mechanism of Resume Reset Logic

Table 16-3 Timing and Voltage Parameters of RSMRST#

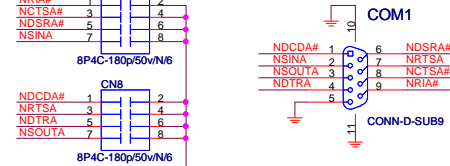
NAME	PARAMETER	MIN.	MAX.	UNIT
V1	3VSB Valid Voltage	-	3.033	V
V2	3VSB Ineffective Voltage	2.882	-	V
t1	Valid 3VSB to RSMRST# inactive	200	300	mS

POWER ON SETTING PIN					
PIN	Name	FUNCTION	0	1	Power
106	COMB_DSW_SEL	COMB_DSW_SEL	UART	DSW	3VBS
51	RTS1#	2E_4E_SEL	2E	4E	3VCC
52	DTR1#	24_48_SEL	24M Clock Source	48M Clock Source	3VCC
54	SOUT1#	GPIO_P0RT80_SEL	GPIO to P0RT80 Disable	GPIO to P0RT80 Enable	3VCC
111	RTS3#	S0UTC_P80_SEL	S0UTC to 80port disable	S0UTC to 80port enable	3VCC
112	DTR3#	S0UTC_P80_SEL	S0UTC to 80port disable	S0UTC to 80port enable	3VCC

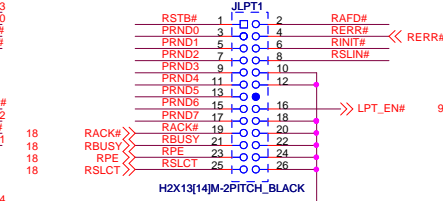
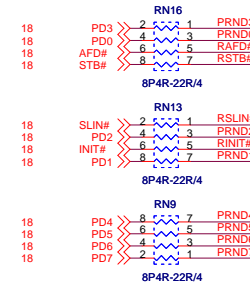
COM PORT 1



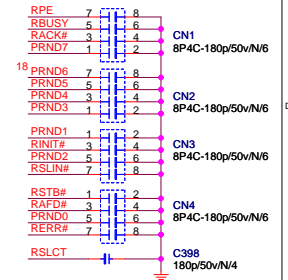
N51-09M0091-F02 change N51-09M0211-F02
2012.10.29



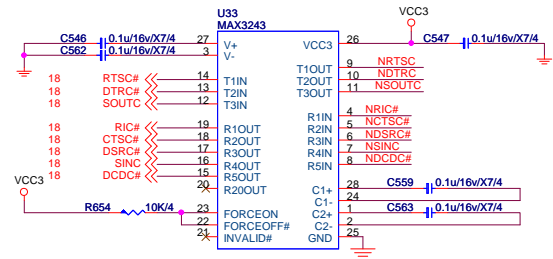
PARALLAL PORT



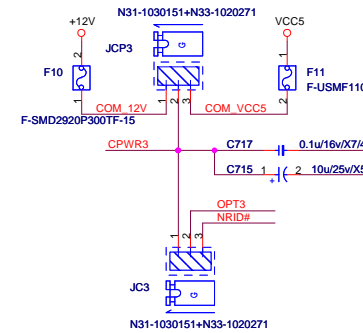
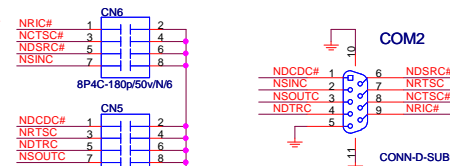
N31-2131281-H06
Vertical
Pitch 2.0 Pin Header



COM PORT 2

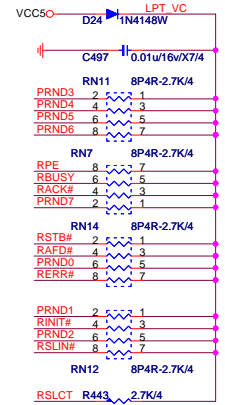


N51-09M0091-F02 change N51-09M0211-F02
2012.10.29

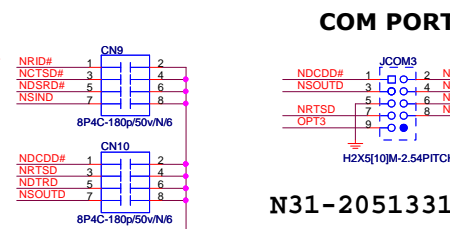
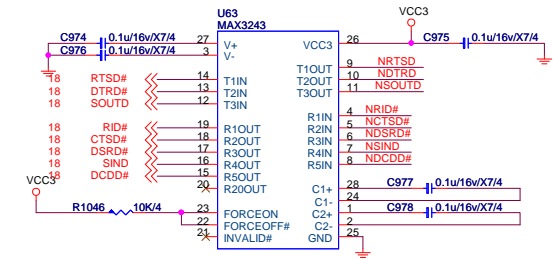


COM3 Function Select

JCP3	1-2	2-3
Fun	12V	5V
JC3	1-2	2-3
Fun	PWR	RIN

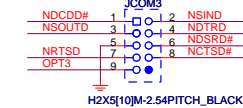


COM PORT 3

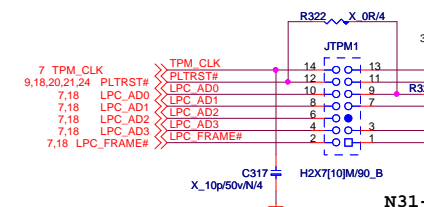


N31-2051331-H06

COM PORT 3

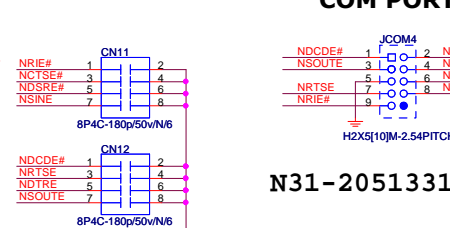
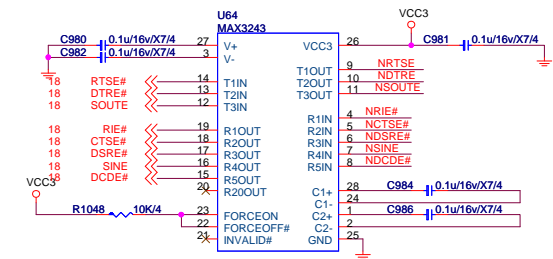


TPM / Port 80 HEADER



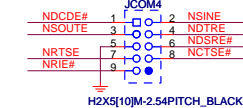
N31-2071201-H06
Right Angle

COM PORT 4

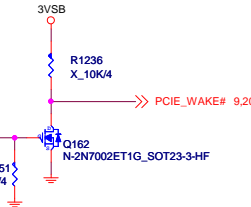
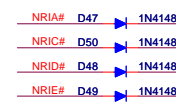


N31-2051331-H06

COM PORT 4

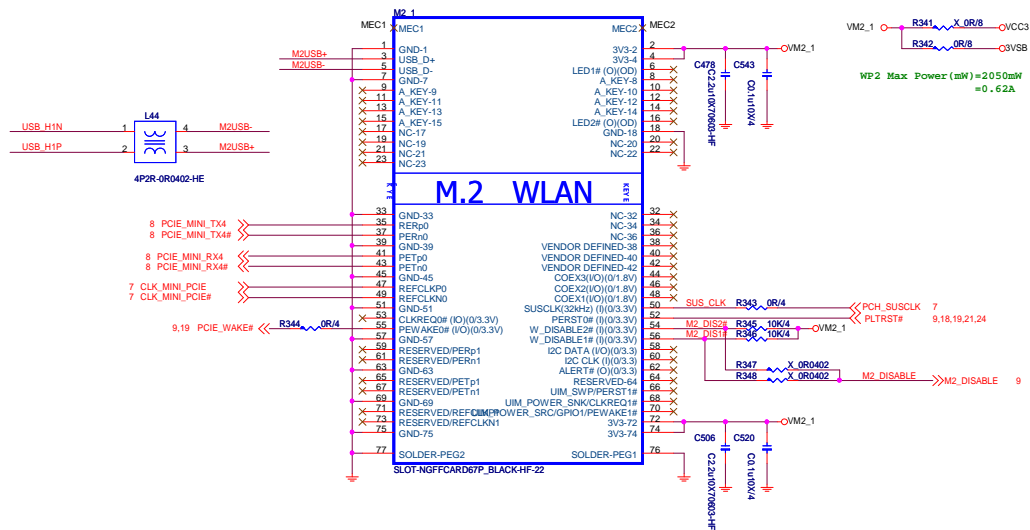


WAKE ON RING



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M.2(USB/PCIE)_E key




for 8.5mm M2

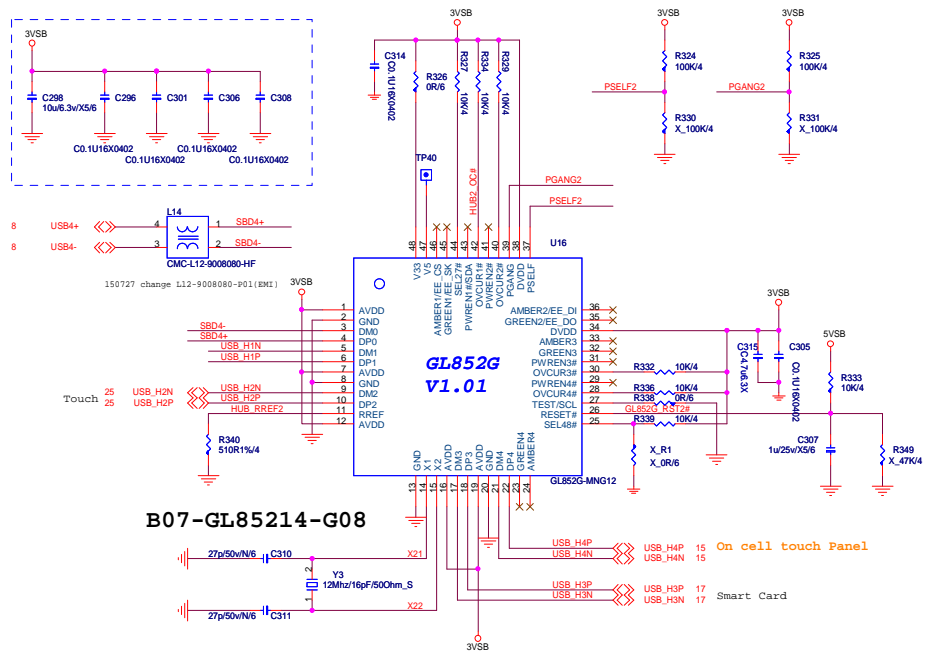
H1

MXM
Stand-off

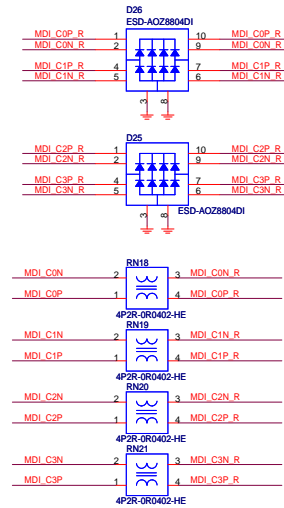
1



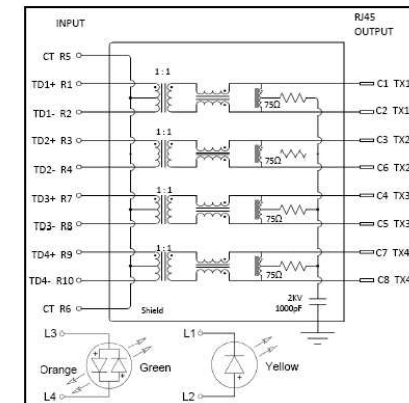
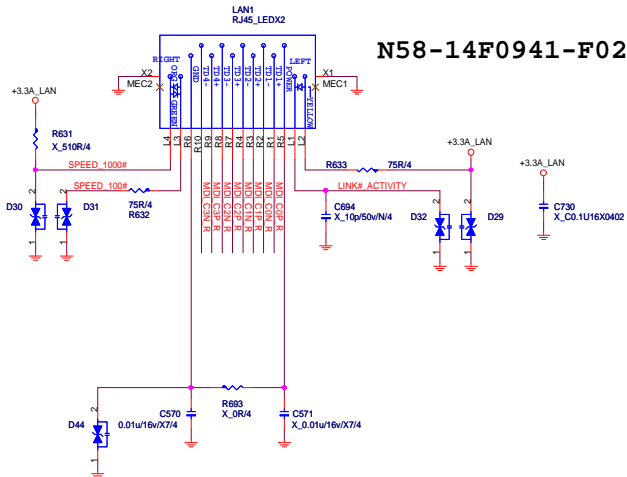
H1 change to E2B-4389010-A89
footprint:H_R220D102_PTB

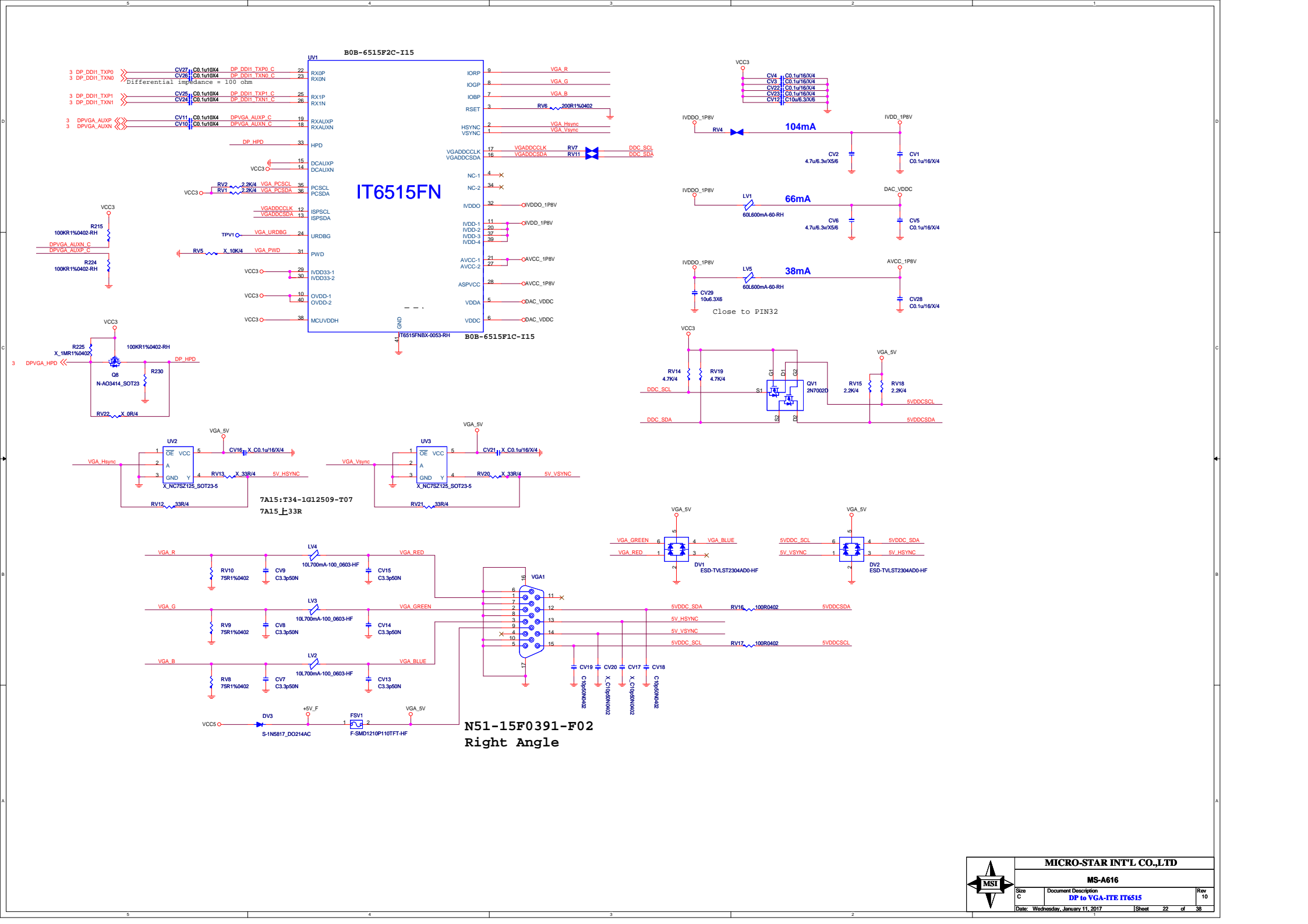


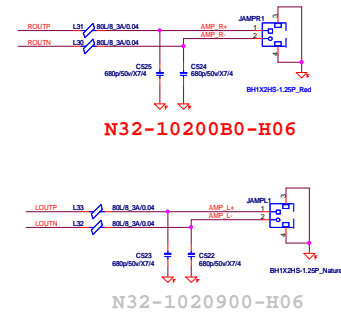
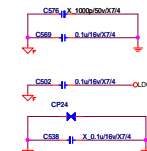
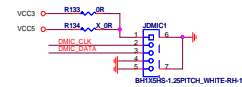
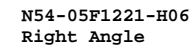
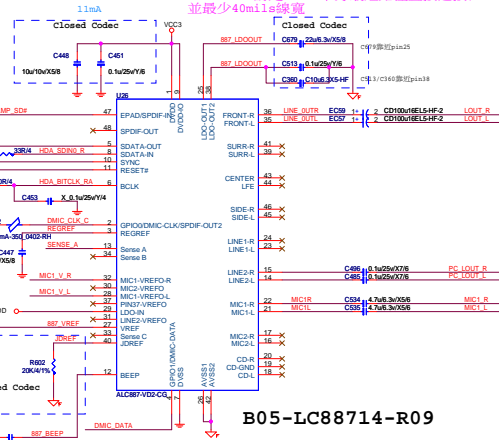
If CLKREQ#2_LAN is connected to PCH,
its PU resistor should be connected to +3.3A_LAN

[illegible]

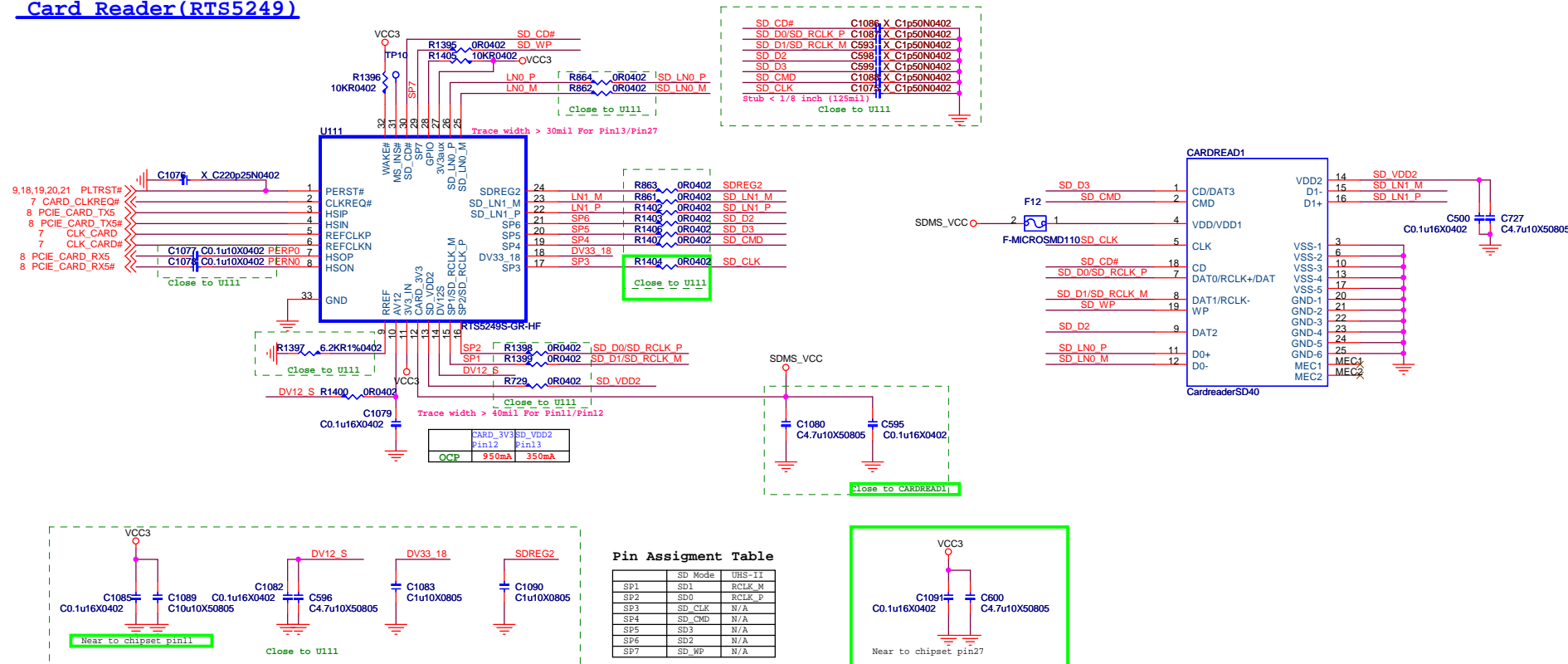
Soft Start Control:
0.1~100ms





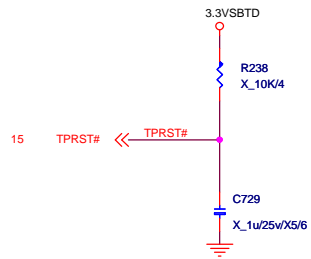
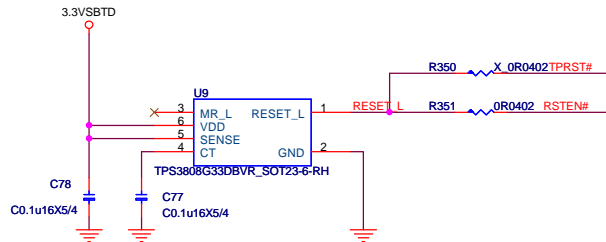
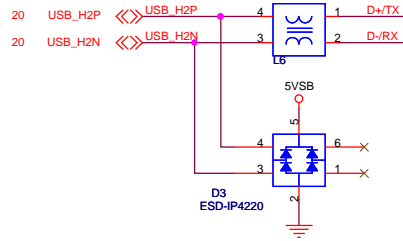


Card Reader(RTS5249)

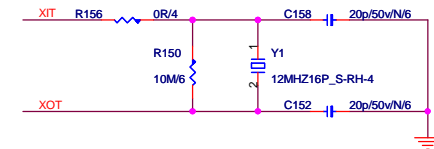
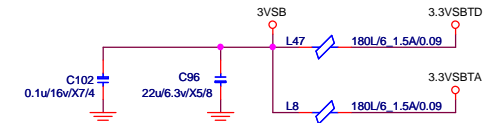
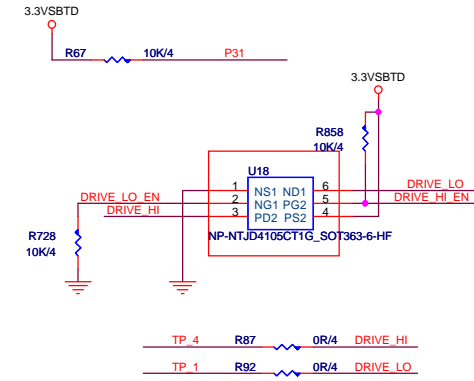
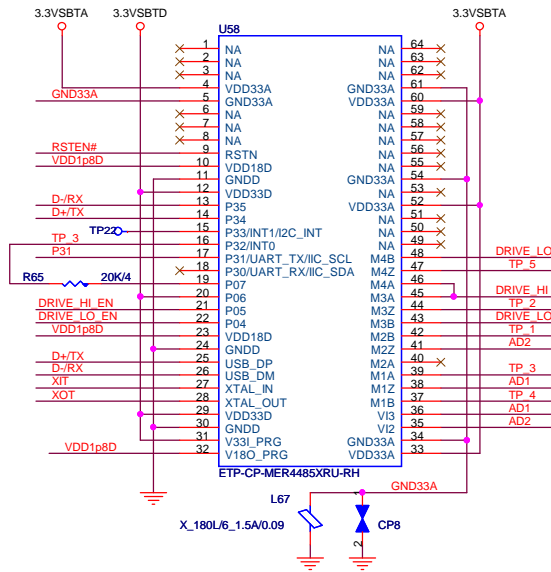


	SD Mode	UHS-II
SP1	SD1	RCLK_M
SP2	SD0	RCLK_P
SP3	SD_CLK	N/A
SP4	SD_CMD	N/A
SP5	SD3	N/A
SP6	SD2	N/A
SP7	SD_WP	N/A

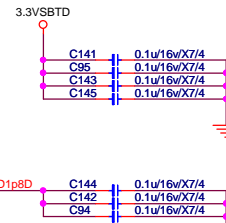
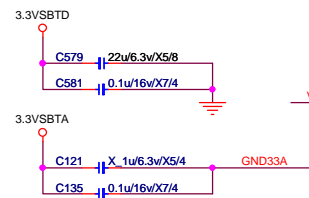
Low Speed USB D+/D-



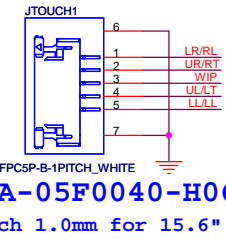
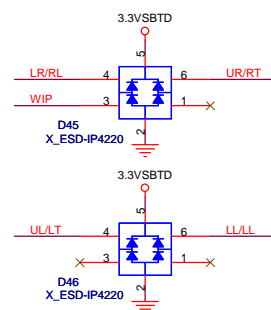
Support On cell touch Panel



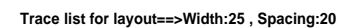
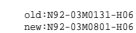
Decoupling Cap.



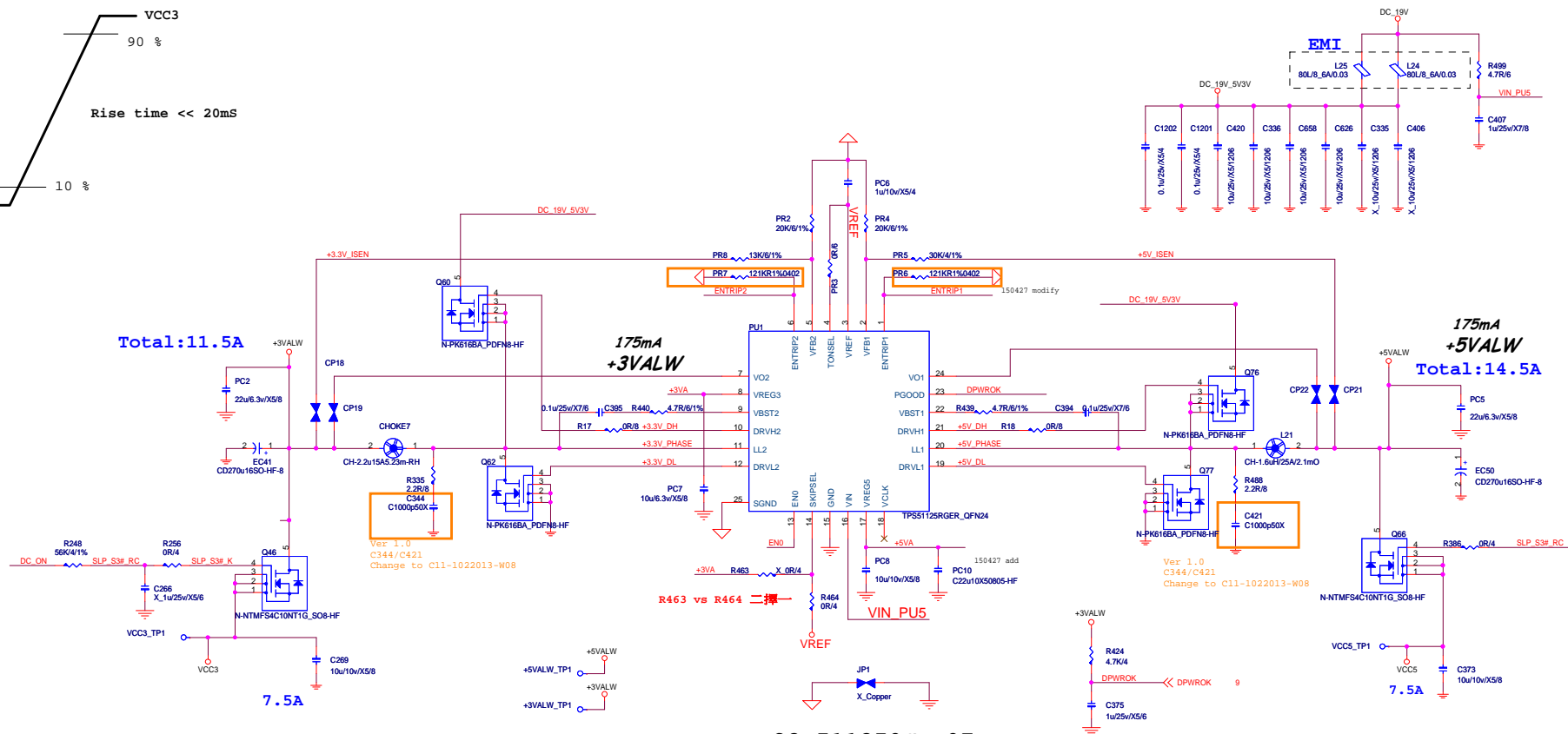
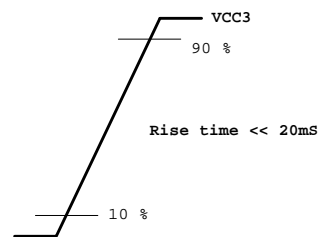
EMI Suppressor



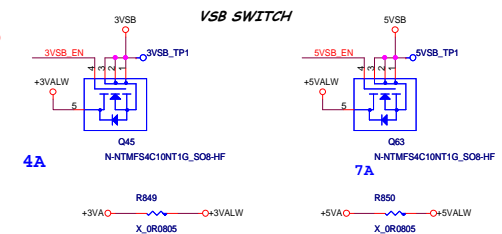
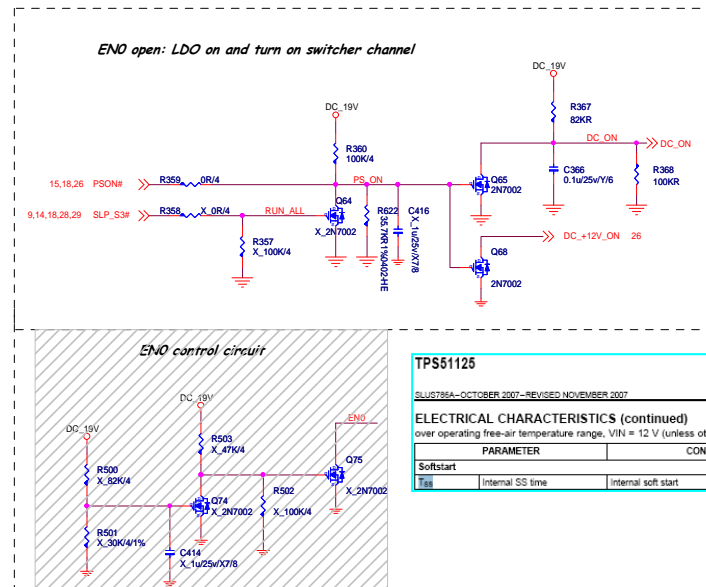
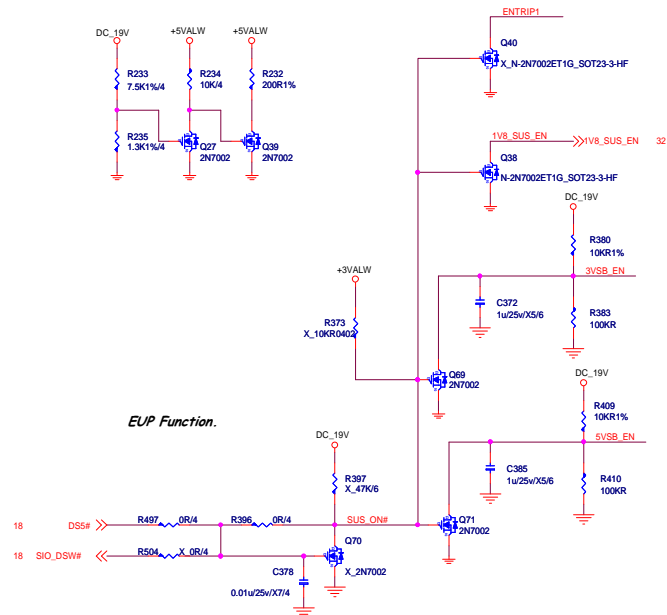
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HG_12V
PHASE_12V
LG_12V



I32-511250C-T07



TPS51125

TEXAS
INSTRUMENT
www.ti.com

SUS726A—OCTOBER 2007—REVISED NOVEMBER 2007

ELECTRICAL CHARACTERISTICS (continued)
over operating free-air temperature range, $V_{IH} = 12\text{ V}$ (unless otherwise noted)

PARAMETER		CONDITIONS	MIN	TYP	MAX	UNIT
Softstart						
Time	Internal SS time	Internal soft start	1.1	1.6	2.1	ms

DDR4

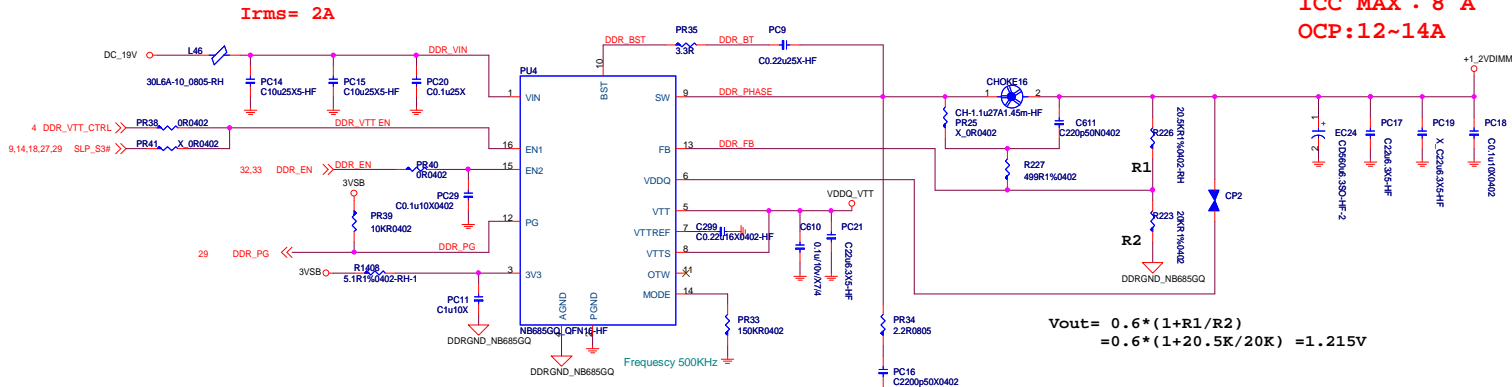
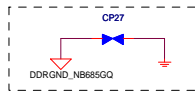


Table 1—EN1/EN2 control

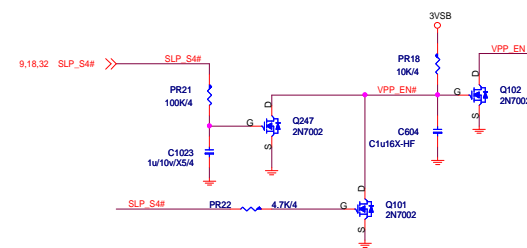
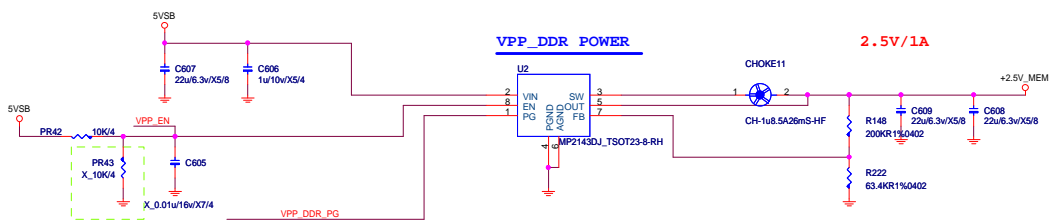
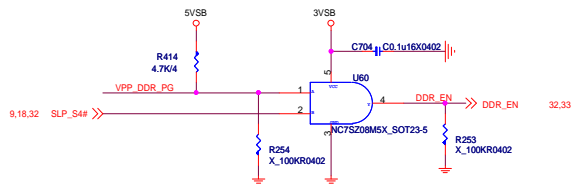
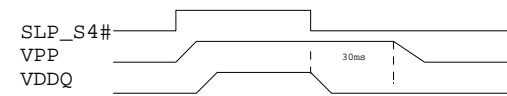
State	EN1	EN2	VDDQ	VTTREF	VTT
S0	High	High	ON	ON	ON
S3	Low	High	ON	ON	OFF(High-Z)
S4/S5	Low	Low	OFF	OFF	OFF
Others	High	Low	OFF	OFF	OFF



```
VTT_DDR : 1/2  DDR
ICC MAX : 1  A
```

$$V_{out} = 0.6 \cdot (1 + R_1/R_2) = 0.6 \cdot (1 + 20.5K/20K) = 1.215V$$

VPP_DDR & VCC_DDR Enable Control

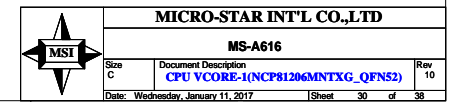


MICRO-STAR INT'L CO.,LTD

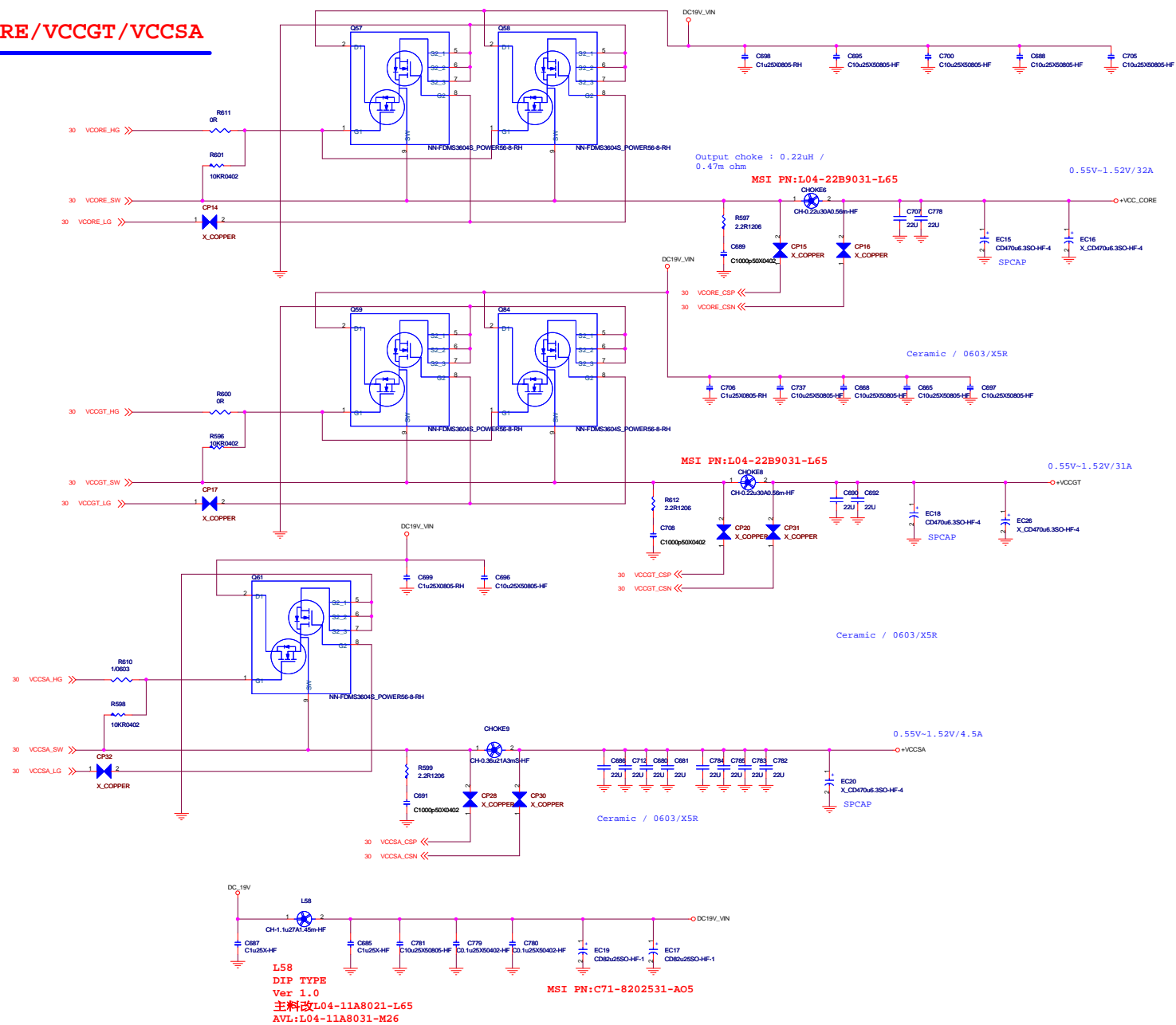
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Vcore Iccmax=29A,
L/L=2.4m ohm
VccGT Iccmax=31A
L/L=3.1m ohm
VccSA Iccmax=5A
L/L=10.3m ohm

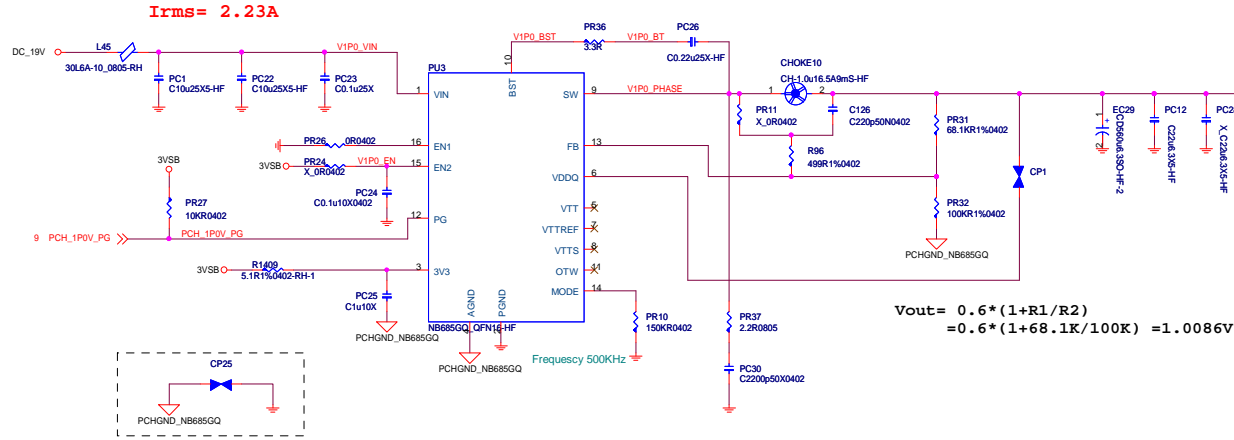


VCORE/VCCGT/VCCSA

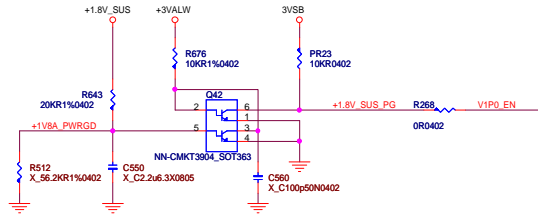


+1.0VSUS **PCH CORE POWER** **PCH_1P0V POWER**

PCH_1P0V : 1.0V
 ICC MAX : 9.132 A
 OCP:12~14A

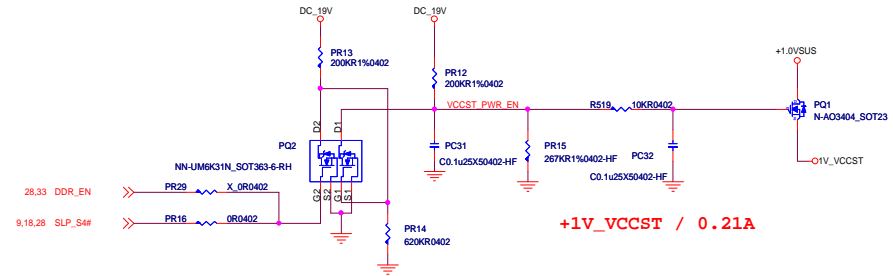
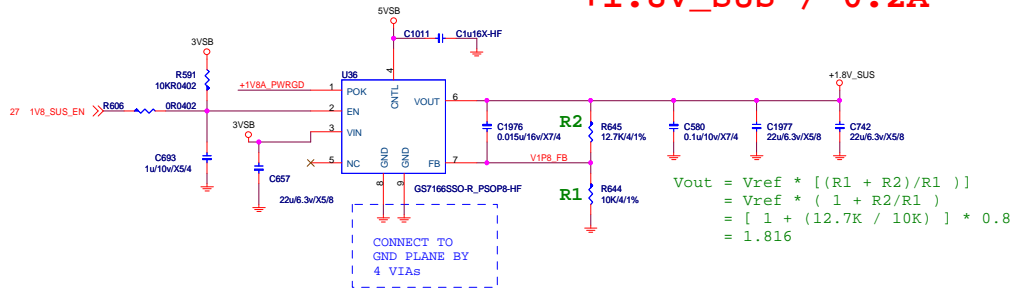


Vo = 1V
 Vin = 19V
 FS = 290kHz
 OCP 150%~200%
 Iout = 9.132A
 Vin_Irms = 1.9A
 MLCC ripple current =
 1.5A*2=3A
 LIR = 25%
 Cin_CAP = 5uF
 Cout_CAP = 669uF
 Cout_CAP_ESR = 4.5m

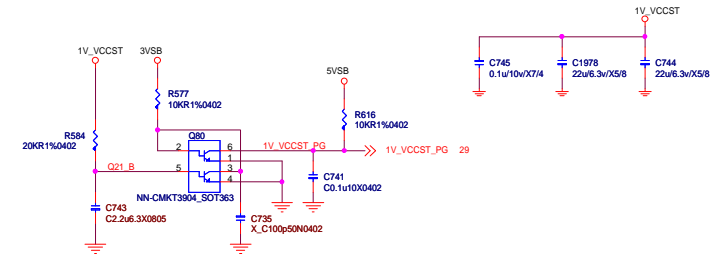


VCCOPC_1p8 may be left on Sx with minimal leakage.

+1.8V_SUS / 0.2A



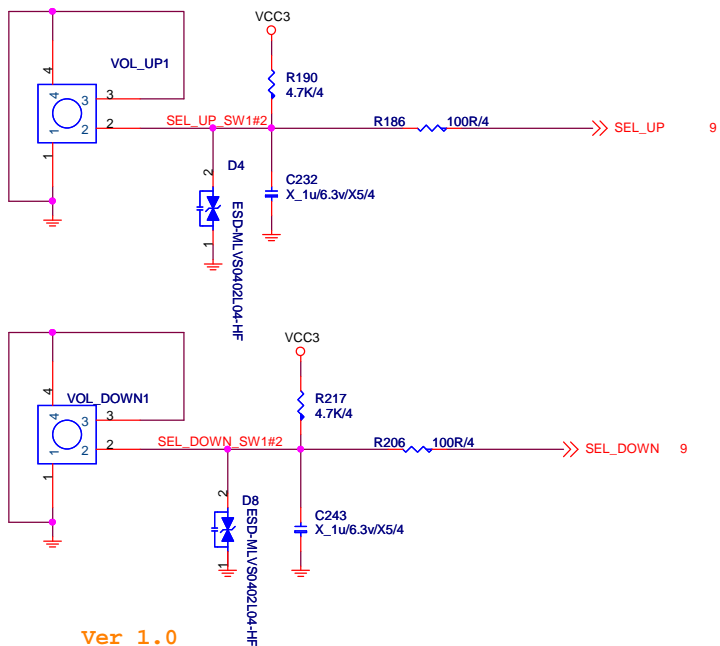
+1V_VCCST / 0.21A



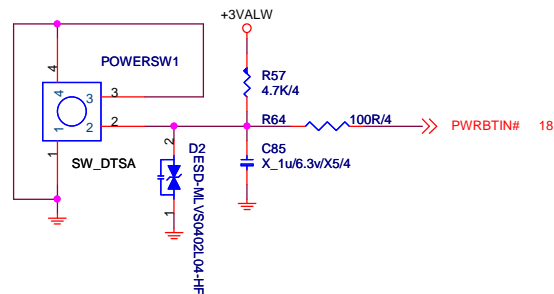
MICRO-STAR INT'L CO.,LTD			
MS-A6161			
Size	Document	+1.0VSUS/+1.8V_SUS/1V_VCCST	
C	Description	Rev 10	
Date: Wednesday, January 11, 2017		Sheet	32 of 38

MODE SELECT CONTROL

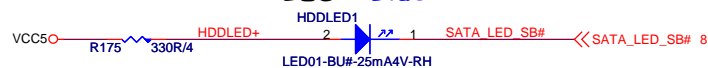
Backlight SEL_UP SEL_DOWN



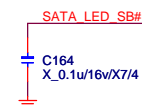
POWER ON/OFF BUTTON



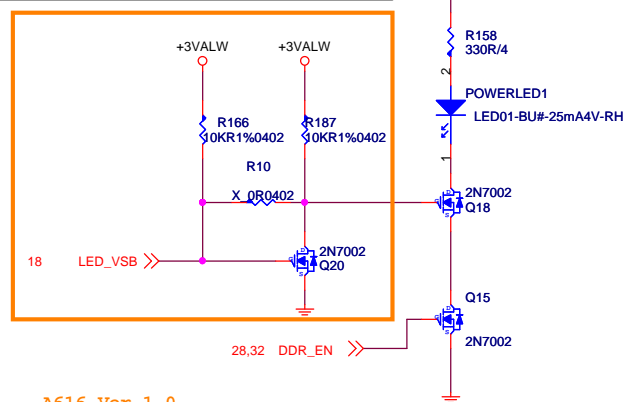
LED Blue



FOR EMI



POWER LED



A616 Ver 1.0
modify power LED circuit



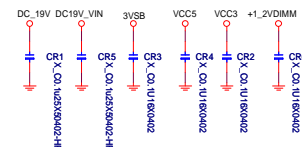
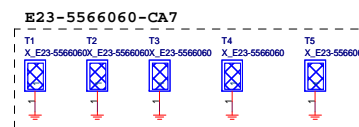
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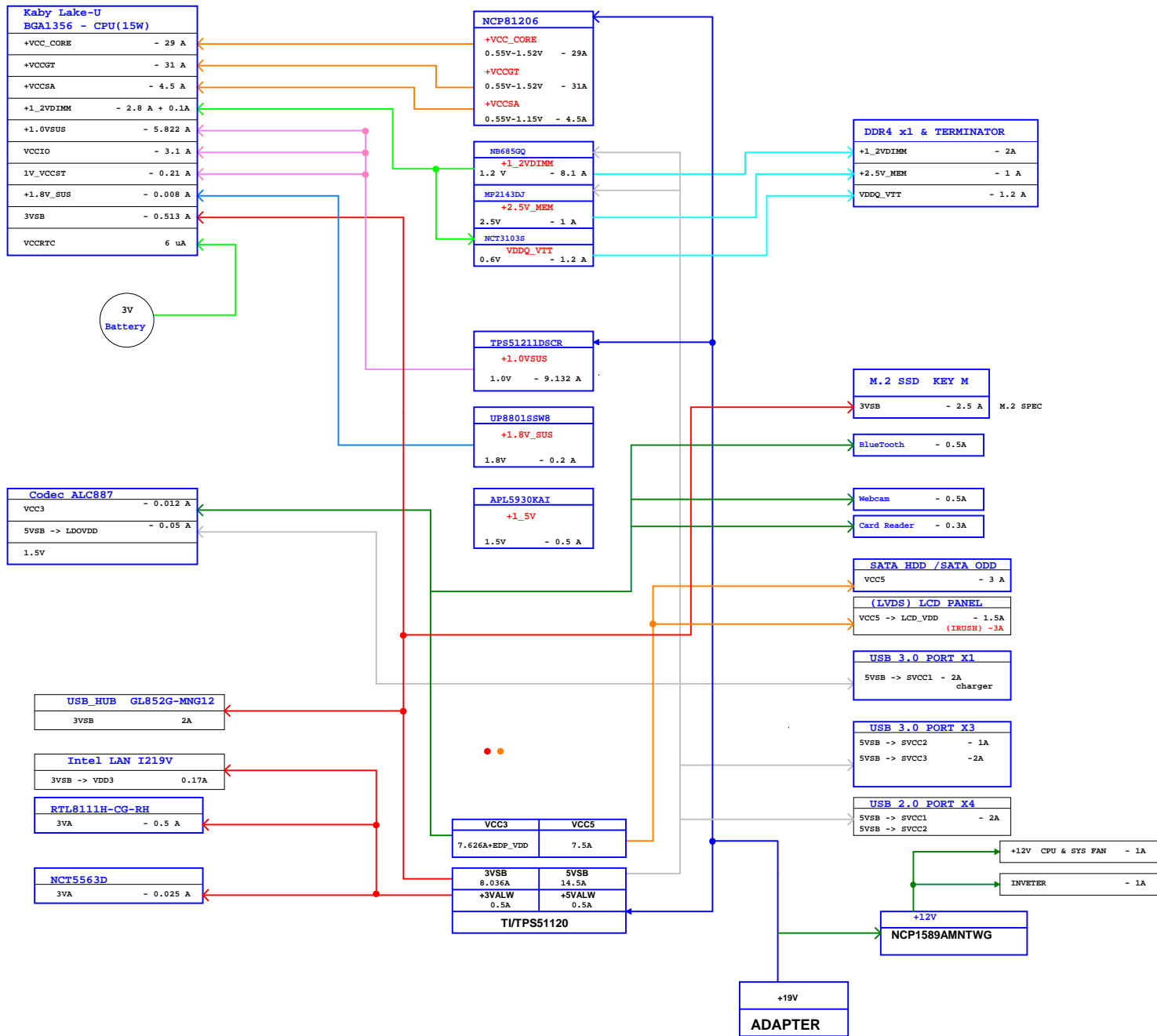
Size B	Document Description	Rev
	HOT KEY / LED	10
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1.0 12/01



FOR RF
2016.11.28



SYS5VSB_OFF

DS5 ---> S0

SYS5VSB_OFF

S0 ---> DS5

VCCRST# (MB-->PCH)

RTCRST# (MB-->PCH)

TPS51125

+5VSB

+3VSB

RSMRST# (By SIO to PCH) (SIO delay 66ms as VSB arrives at 2.95V)

up: 2.95V down:2.35V

RSMRST C# (By RSMRST# to PCH) (SIO delay 66ms as VSB arrives at 2.95V)

up: 2.95V down:2.35V

PWRBTIN# (to SIO to PCH) (CP Internal 16ms debounce)

SLP S5# (By PCH to SIO)

SLP S4#

SLP S3# (By PCH to SIO)

PSON# (By SIO to PS)

+12V (By PS to MB)

VCC5 (By PS to MB)

VCC3 (By PS to MB)

+2.5V_MEM (VFP)

NB685GQ

+1_2VDIMM (VDDQ)

VCCIO

VDDQ_VTT (By CPU_VTT)

VCORE_EN

VCC_CORE

NCP81206

+VCCSA

VCCGT

ATXPGD (By PS to SIO 12V/5V/3V Delay 100ms-500ms)

CHIP_PWROK (By ATX_POK & 3V & S3#) (SIO to PCH) (delay 400ms)

DDR_PG (By PCH to CPU) (as CHIP PGD)

PCH_CLK (By PCH to CPU) (as mem PGD)

SYS_PWROK (PCH to CPU) CPU: 5ms min*2, 650ms max

SVID (By VR_EN Ready (>Vih)) (5ms max, VR_EN)

VIDALERT# (By VCCP Ready)

PLTRST# (PCH to CPU) (By PCH to CPU/SIO) (2-21-->2-22 delay > 1ms)

+5VSB

+3VSB

RSMRST#

+1.0VSUS (as +12V)

VDDQ_VTT (as +12V)

+1.8V_SUS (as +12V & 3V)

VDDQ_VTT

+1_2VDIMM (as S4#)

+12V/VCC5/VCC3 (as ATX_POK)

ATXPG (as PSON#)

PSON#

SLP_S5#

DDR_PG (as S4#) (must fall before S4# or within 100ns)

SL_S4# S3-->S4-->S5: min 30us

VCORE_EN (as CPU_SA) T: ????

+VCCSA (as S3#) S3-->S4-->S5: min 30us

CHIP_PWROK (as S3#)

SLP_S3#

VRM_PGD (as VCCP)

VCC_CORE (as VIDALERT#)

VCCGT (as VIDALERT#)

VIDALERT# (as SVID)

SVID (as CPUPWROK)

PCH_CLK

SYS_PWROK (PLTRST#-->CPUPWOK >30us)

PLTRST#

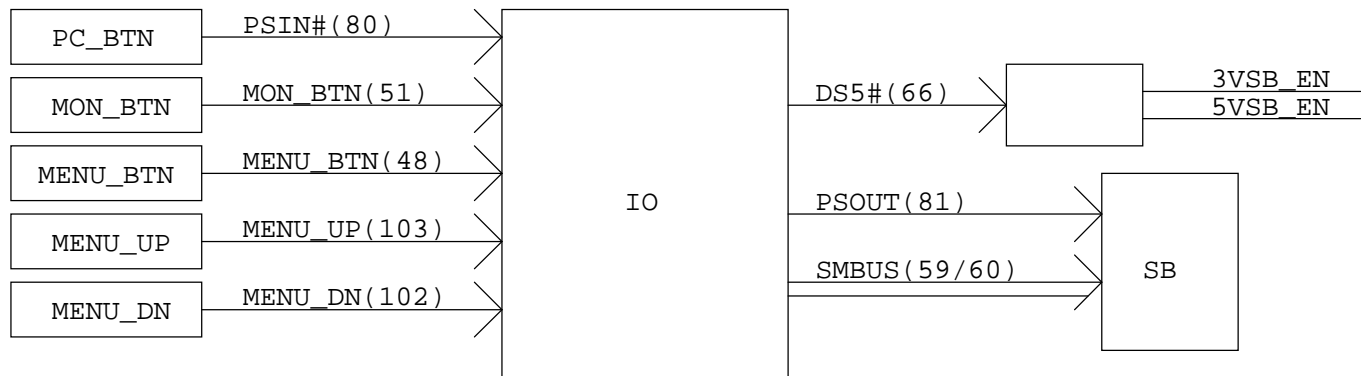
CPURST#



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MS-A616

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A616 Schematic History
PCB 0A Hostory

2016/10/28
change CPU Kaby lake-U

2016/11/02
Add Power suggestion

A616 Schematic History
PCB 1.0 Hostory

2016/12/23
Page 27 PR6 /PR7 change to 0402 type
Page 26 R1290 change to 6.65K

2017/01/03
Page 33 modify backlight button circuit

Page 16 Part reference change
SATA1 : for ODD / SATA2 : for HDD

Page 17 (Modify) add USB2.0 OC circiut

Page 34 Modify M5 footprint same as M7

Page 33 (Modify) POWER LED circuit

BOM Modify

Page 11 R171 / R182 change to R11-0000012-W08

Page 28 R226 change to R11-2052T12-W08

Page 28 / 31 CHOKE16 / L58 DIP TYPE Ver 1.0
主料改L04-11A8021-L65 , AVL:L04-11A8031-M26

Page 14 U30 Ver 1.0
主料改I36-7550P09-U33

Backlight issue SEL_UP SEL_DOWN
Page 9 R114 / R115 unstuff

Page 27 C344/C421 Ver 1.0
更改C11-1022013-W08為主料號

Page 15 Ver 1.0
C54 change to C11-1047512-W08

Page 23/26 Ver 1.0
C678/C1195 change to C11-2212812-W08 為主料號

Page 05 Ver 1.0
C34 change to C11-2232032-W08 為主料號

Page 05/20 Ver 1.0
C14/C478/C506 change to C11-2252413-S02 為主料號

Page 17 Ver 1.0
C701/C738 change to C11-4712012-W08 為主料號

Page 19/26 Ver 1.0
Q162/Q1150 change to D03-7002E89-005為主料號

Page 33 Ver 1.0
HDDLED+/POWERLED1 change to D0C-010C901-E07為主料號